

Overview

Who is Resonetics?

Mission

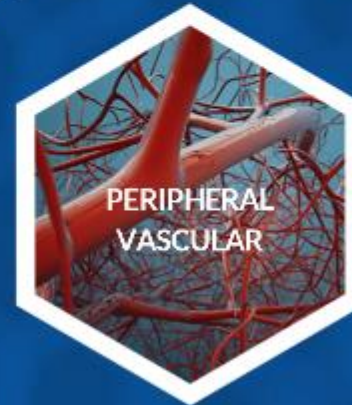
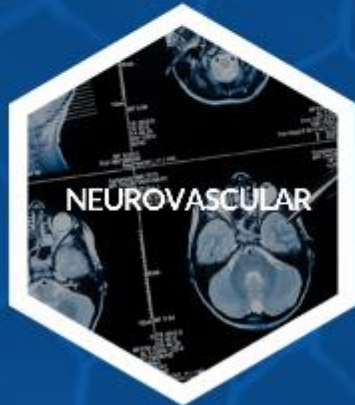
Resonetics will be the leader in laser micro manufacturing for the life sciences industry by providing innovative solutions and unrivaled customer service.

- Expertise in polymers, metals, glass and ceramic
- Unparalleled innovation with engineering resources
- State-of-the-art facilities and equipment
- Locations: Boston, Dayton, San Diego, Costa Rica, Minneapolis

Values

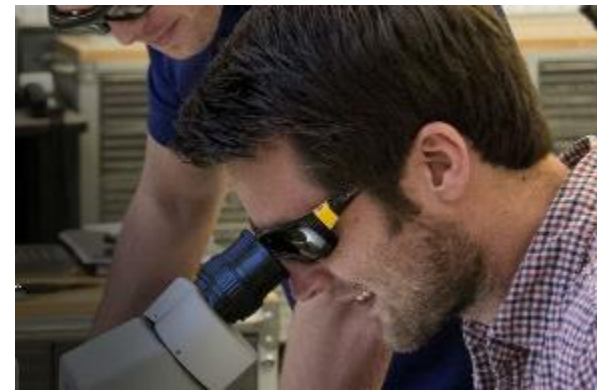
Creativity | Urgency | Quality | Integrity | Respect

Who Do We Help?



Who is Resonetics?

- 270 employees including 50 engineers and 5 Ph.D.'s
- 5 state-of-the-art facilities with 113,000 sq. ft.
- 75 laser workstations with 13 ultrafast lasers
- Lightspeed ADL™ prototyping & process development capabilities in Nashua, Kettering, and Plymouth facilities
 - 18 laser workstations
 - 21 engineers and technicians
- Clean room manufacturing in all 5 sites
- 90% of revenues in the life sciences industry
- 89% of revenues are contract manufacturing (11% systems/spares/service)
- Produce >16 million parts per year



Locations

WE HAVE FIVE LOCATIONS

Our world class laser micro manufacturing facilities include 24/7 operations, 5 cleanrooms, 3 Lightspeed ADL™ development centers, over 75 laser systems and more than 250 team members.



Contract
Manufacturing
Lightspeed ADL
Systems Group
55,000 Sq. Ft.

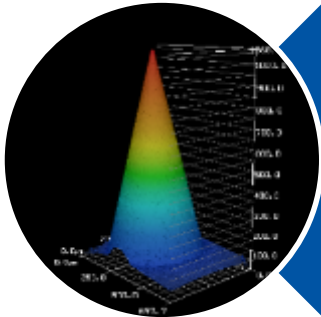
Contract
Manufacturing
20,000 Sq. Ft.

Contract
Manufacturing
Lightspeed ADL
20,000 Sq. Ft.

Contract
Manufacturing
Lightspeed ADL
9,000 Sq. Ft.

Contract
Manufacturing
9,000 Sq. Ft.

Business Model



Advanced Technology Group

Next Generation Laser Micro Manufacturing
Technology



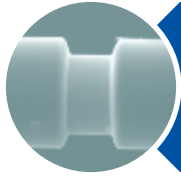
Quick Turn Prototypes



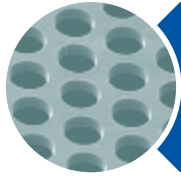
Contract Manufacturing

Volume Production
Custom Laser Systems

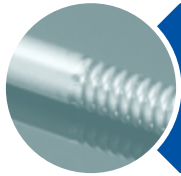
Technologies



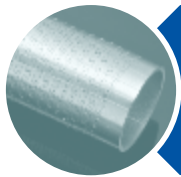
Ablating



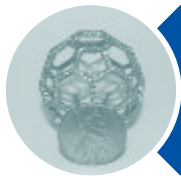
Drilling



Welding

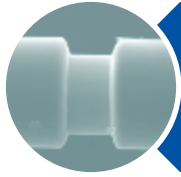


Cutting

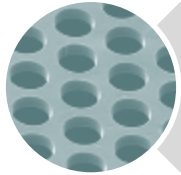


Additive

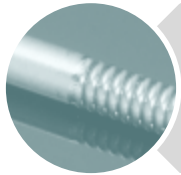
Technologies



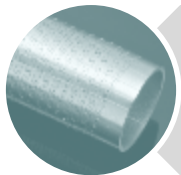
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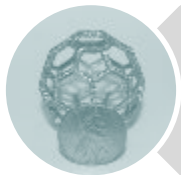
Drilling



Welding

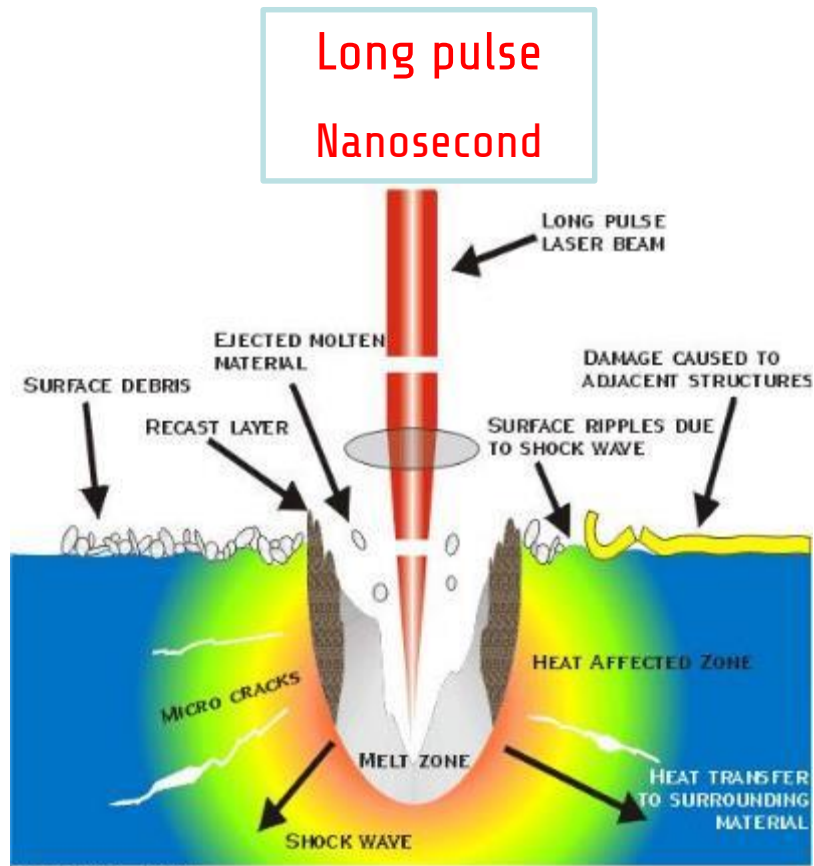


Cutting

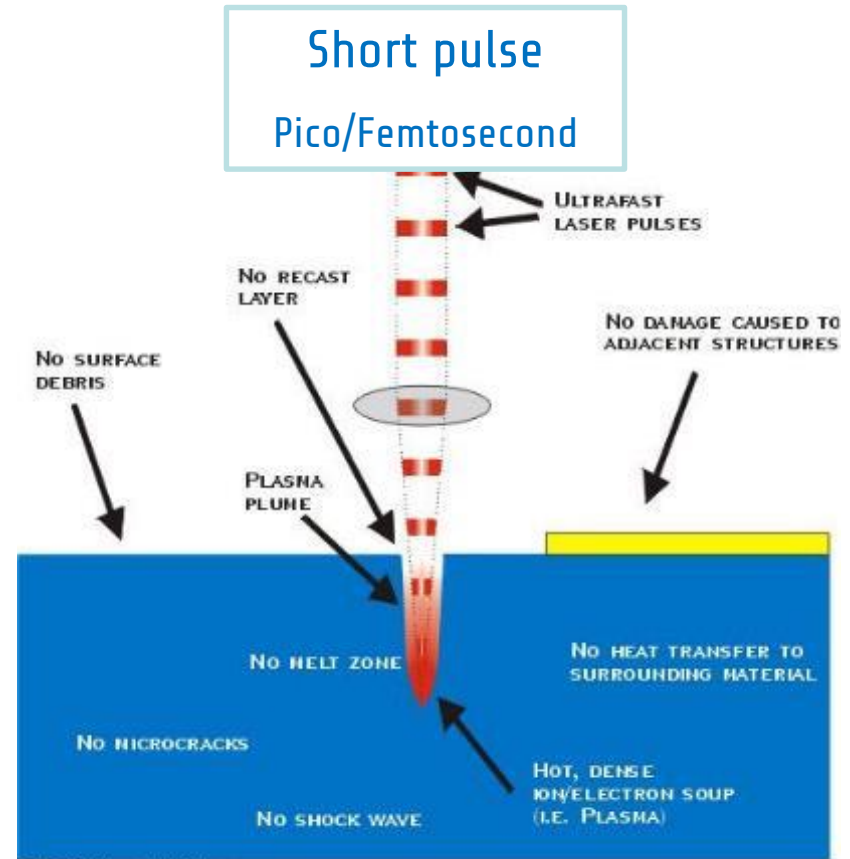


Additive

Pulse Duration - Long vs. Short Pulse



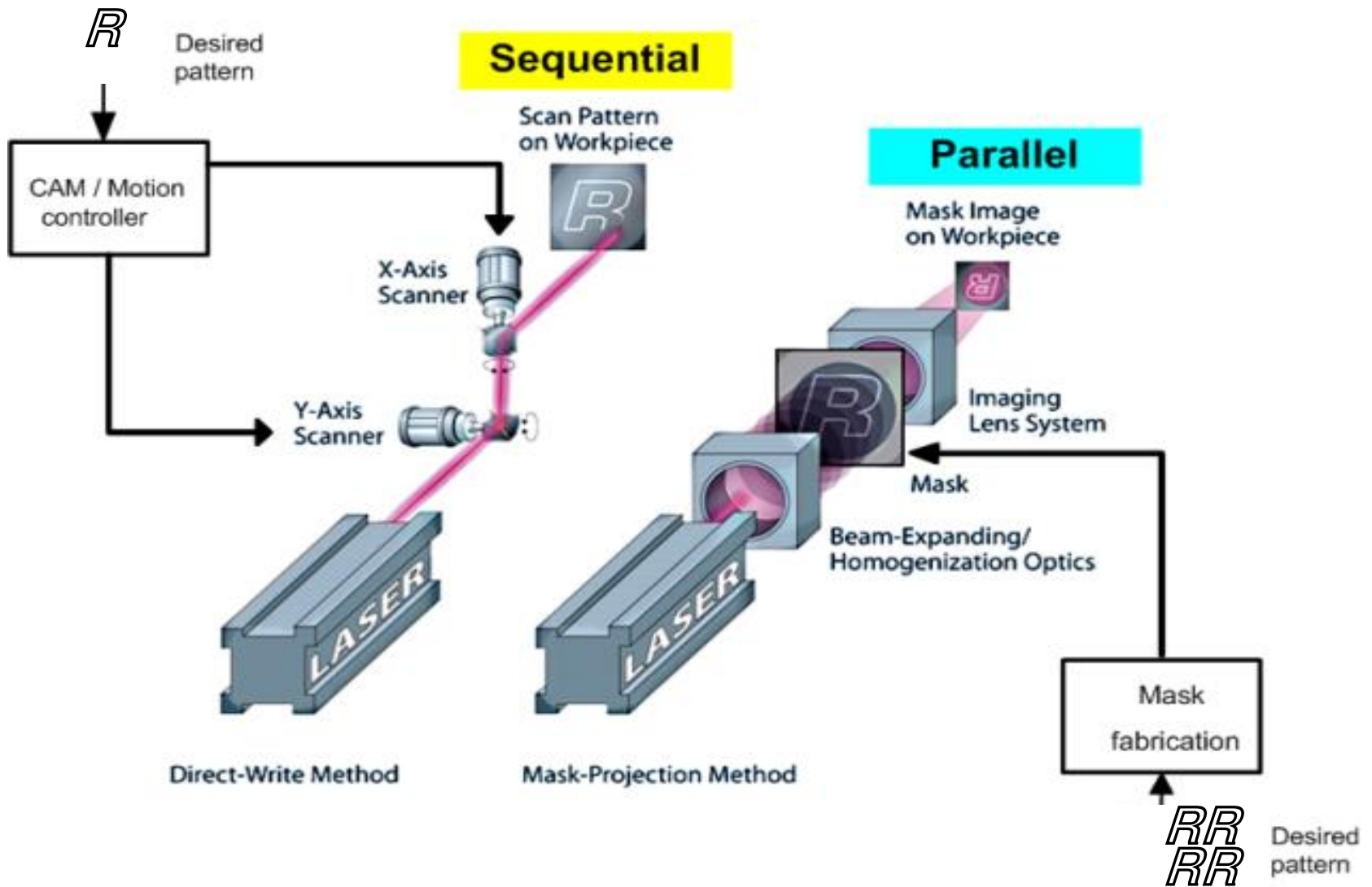
©1999 Clark-MXR, Inc.



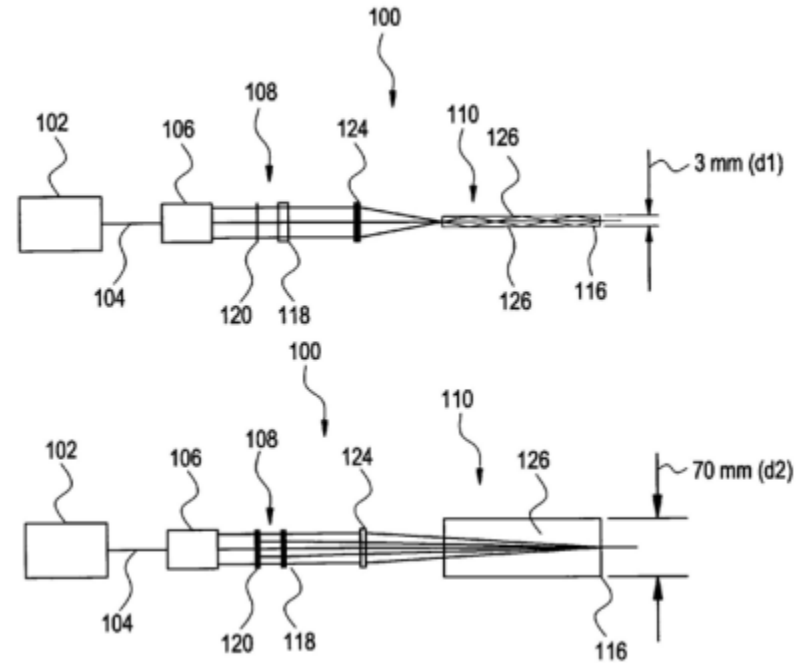
©1999 Clark-MXR, Inc.

- + multi-photon absorption
- all materials
- sub-resolution

Direct Write and Mask Projection



Braided Catheter



(12) **United States Patent**
Broude et al.

(10) **Patent No.:** **US 7,210,820 B2**
(45) **Date of Patent:** **May 1, 2007**

(54) **METHODS AND APPARATUSES FOR
HOMOGENIZING LIGHT**

(56)

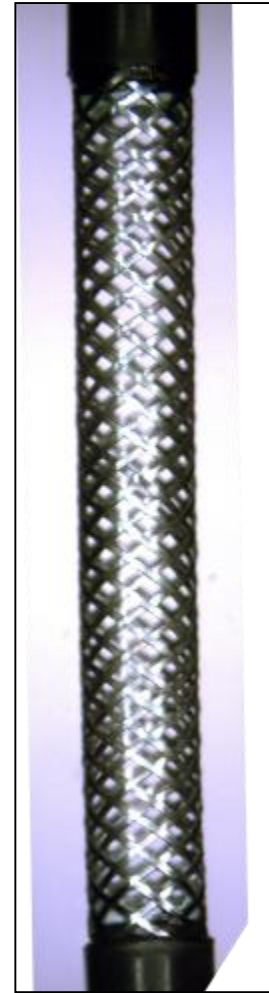
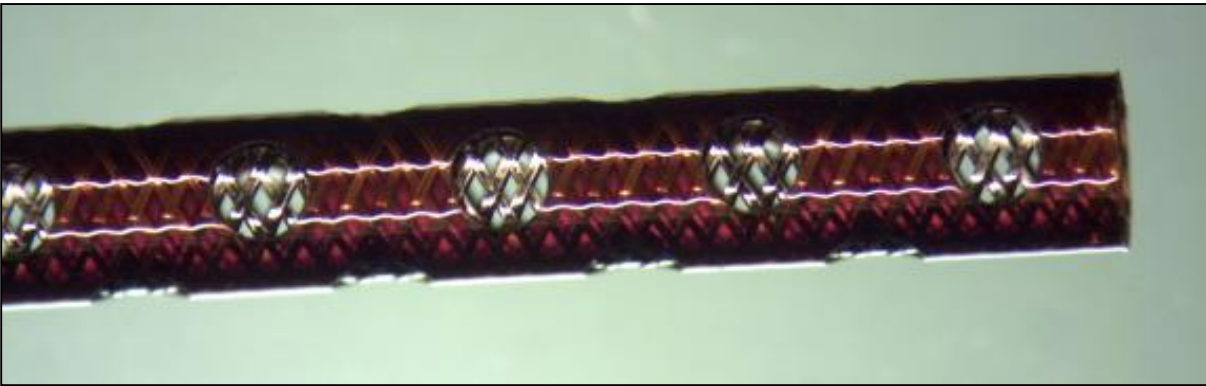
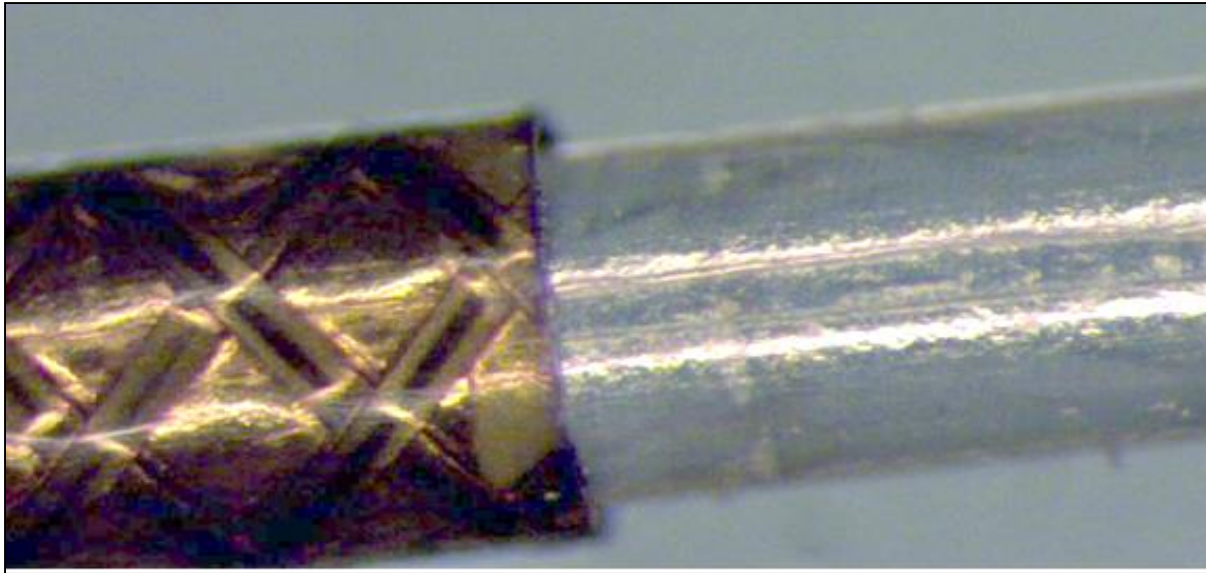
References Cited

U.S. PATENT DOCUMENTS

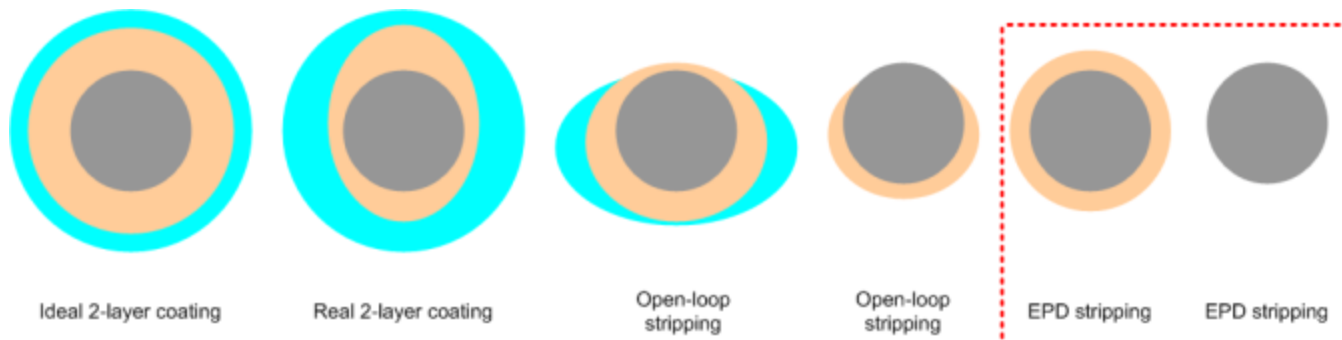
(75) Inventors: **Sergey V. Broude**, Newton Centre, MA (US); **David S. Holbrook**, Lexington, MA (US); **Pascal Miller**, North Chelmsford, MA (US)
(73) Assignee: **Resonetics, Inc.**, Nashua, NH (US)

| | | | |
|---------------|---------|------------------------|------------|
| 4,744,615 A | 5/1988 | Wilczynski et al. | 350/96.1 |
| 4,918,583 A | 4/1990 | Kudo et al. | 362/268 |
| 5,109,465 A | 4/1992 | Klopotek | 385/133 |
| 5,721,416 A | 2/1998 | Burghardt et al. | 219/121.73 |
| 5,946,138 A * | 8/1999 | Mizouchi | 362/259 |
| 6,002,101 A * | 12/1999 | Yamazaki et al. | 359/622 |

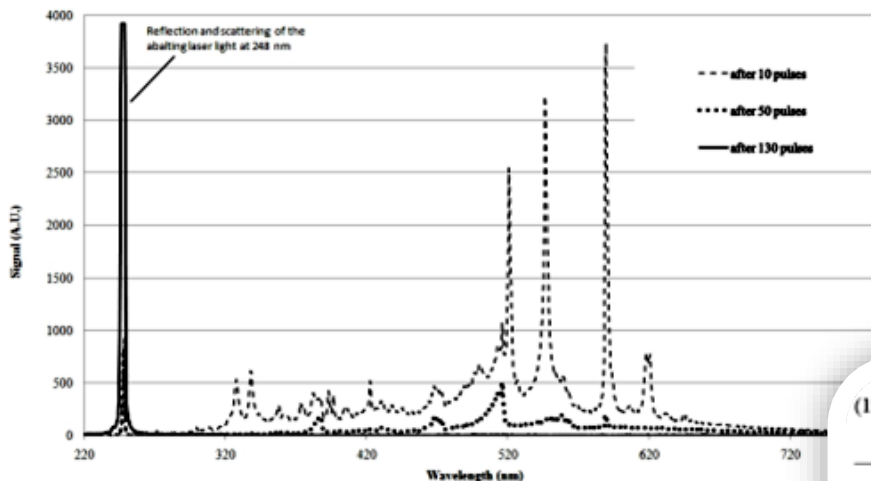
Braided Catheter



Wire Stripping – Assure End-Point Detection™



Emission Spectra Progression



(12) **United States Patent**
Broude et al.

(10) **Patent No.:** US 8,772,671 B2
(45) **Date of Patent:** Jul. 8, 2014

(54) **PRECISION LASER ABLATION**

(56) **References Cited**

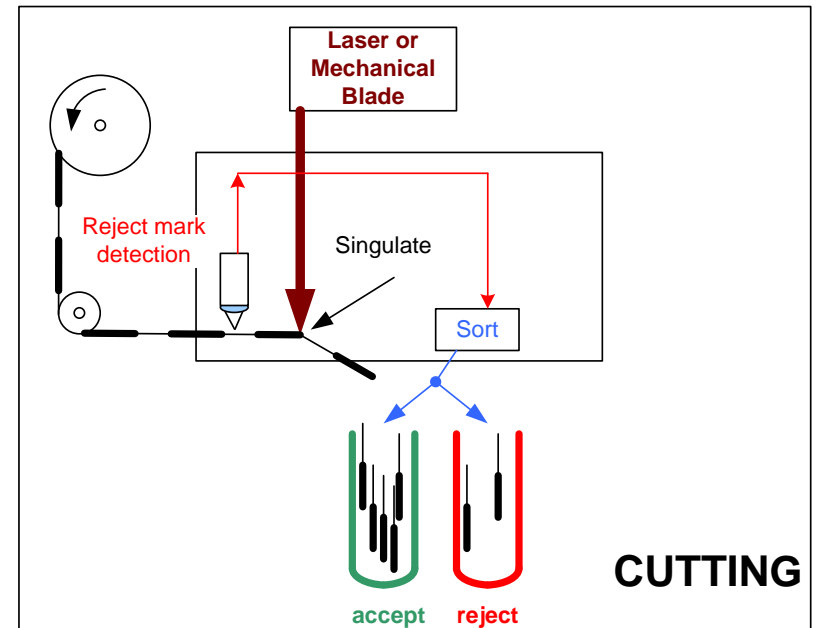
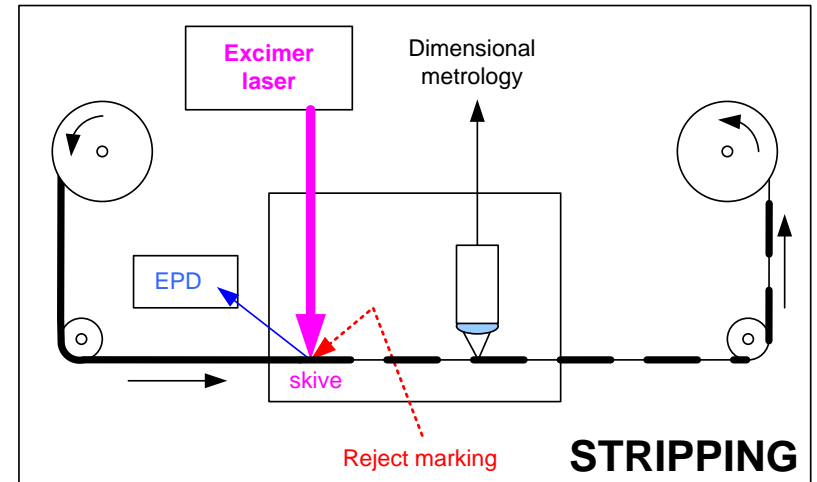
(75) **Inventors:** Sergey V. Broude, Newton, MA (US);
Chen-Hsiung Cheng, Westford, MA
(US); Pascal Miller, Groton, MA (US);
Glenn Ogura, Oakley, CA (US); David
L. Wall, Burlington, MA (US)

U.S. PATENT DOCUMENTS
4,626,652 A 12/1986 Bjork et al.
5,011,626 A * 4/1991 Ma et al. 252/582
5,204,517 A * 4/1993 Cates et al. 219/121.62
5,281,798 A * 1/1994 Hamm et al. 219/121.62

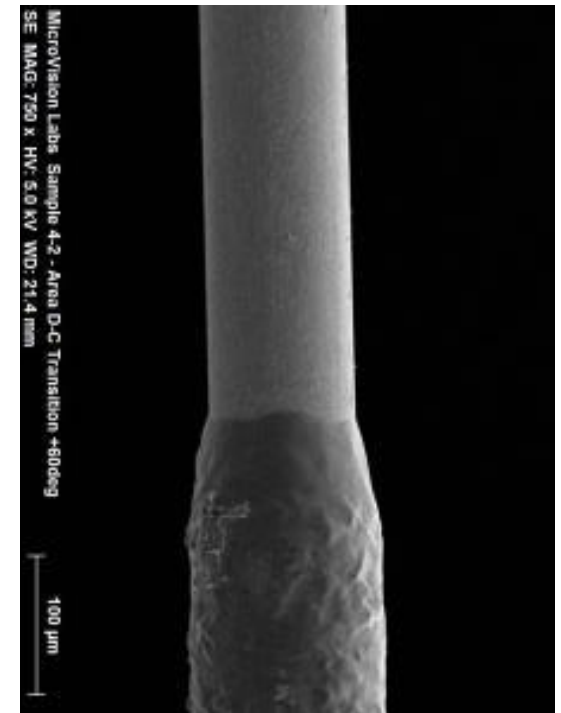
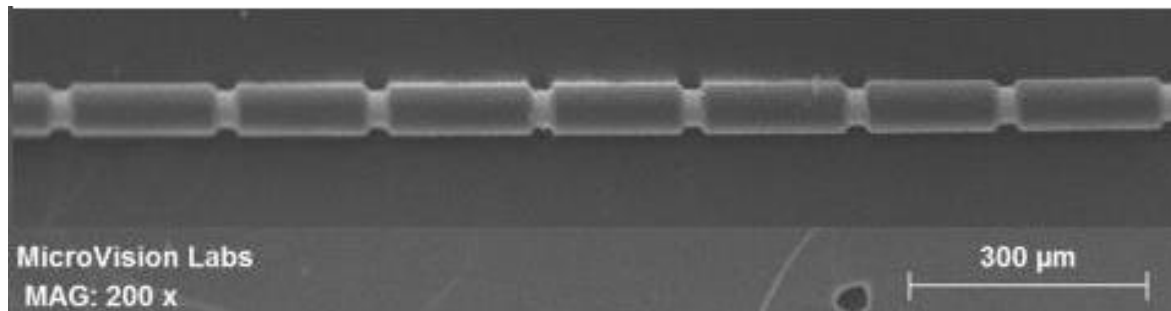
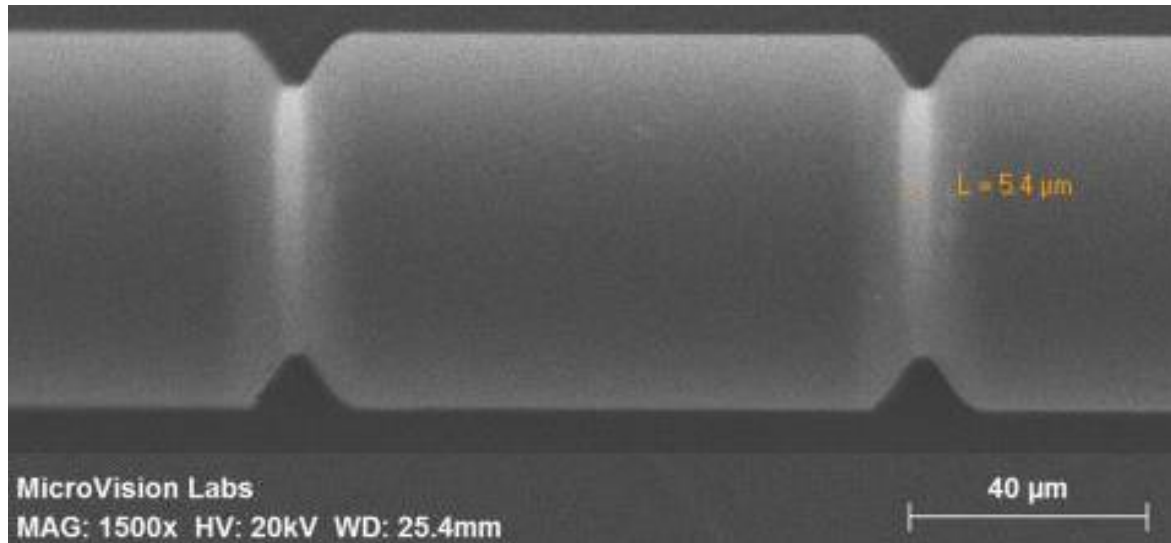
(73) **Assignee:** Resonetics, LLC, Nashua, NH (US)

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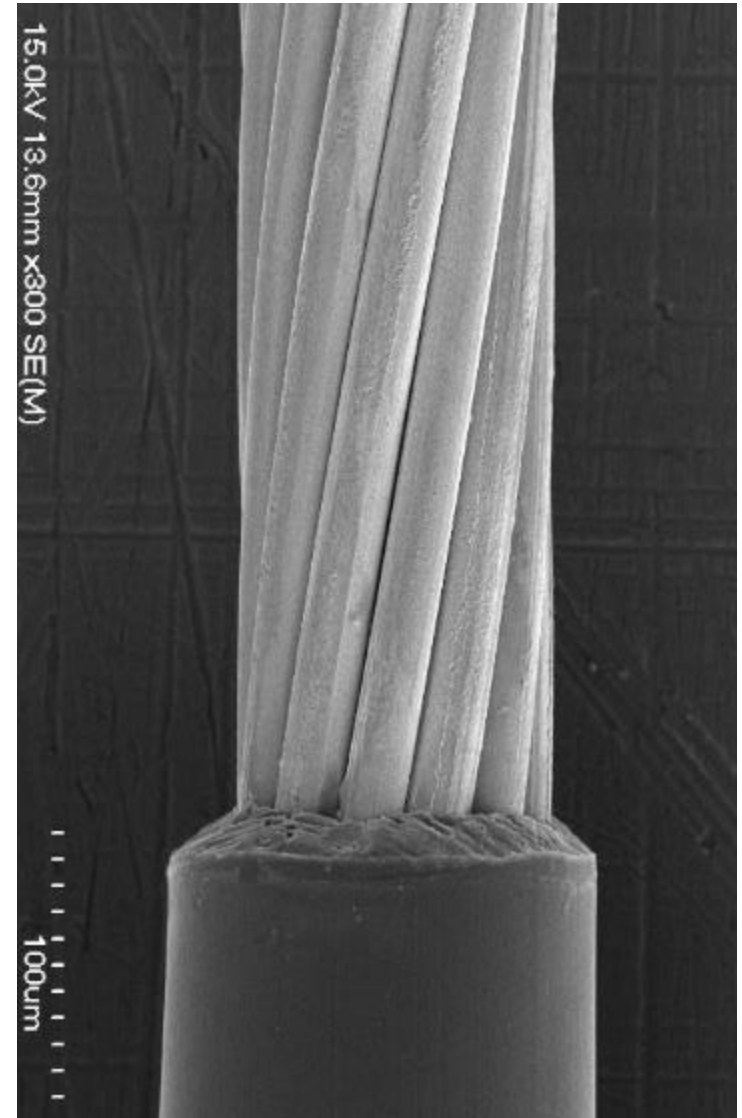
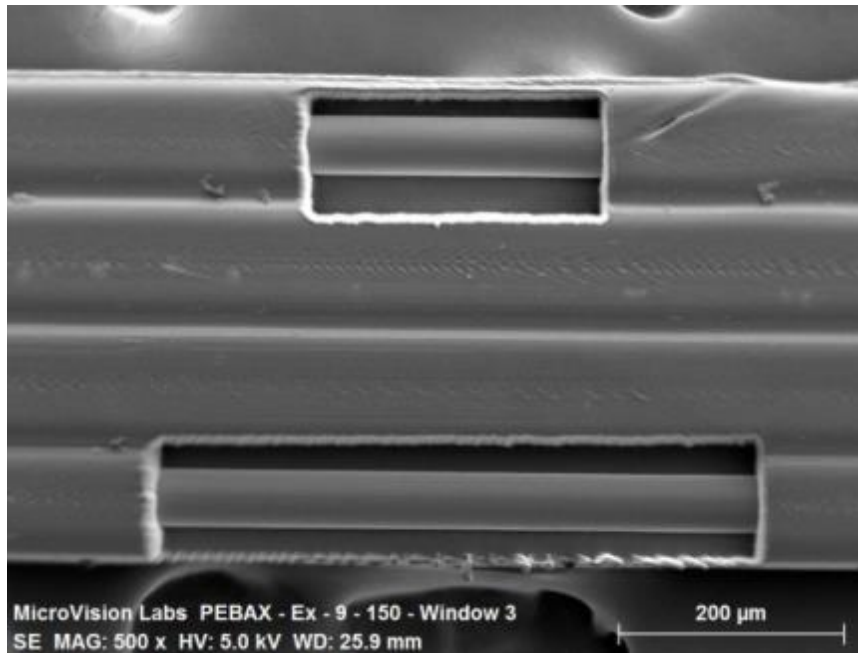
Reel-to-Reel Wire Stripping System



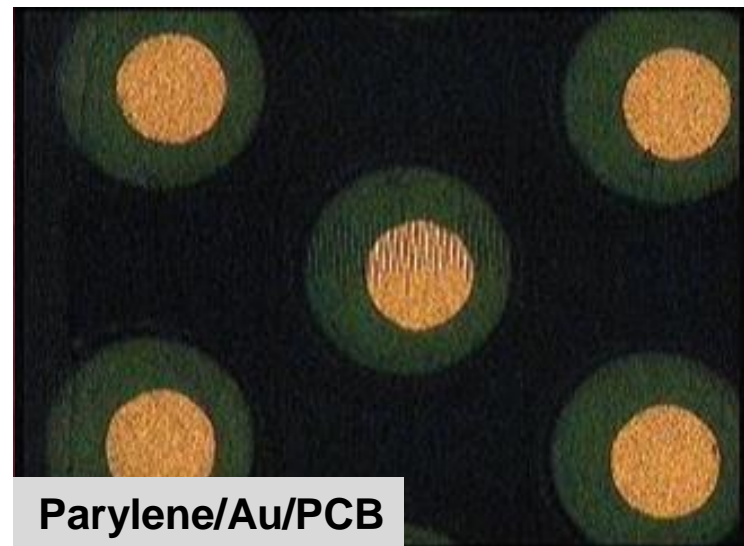
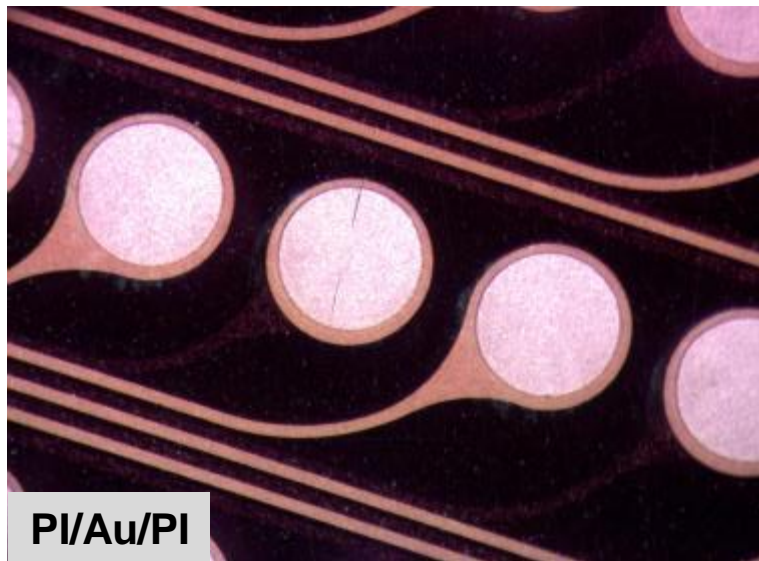
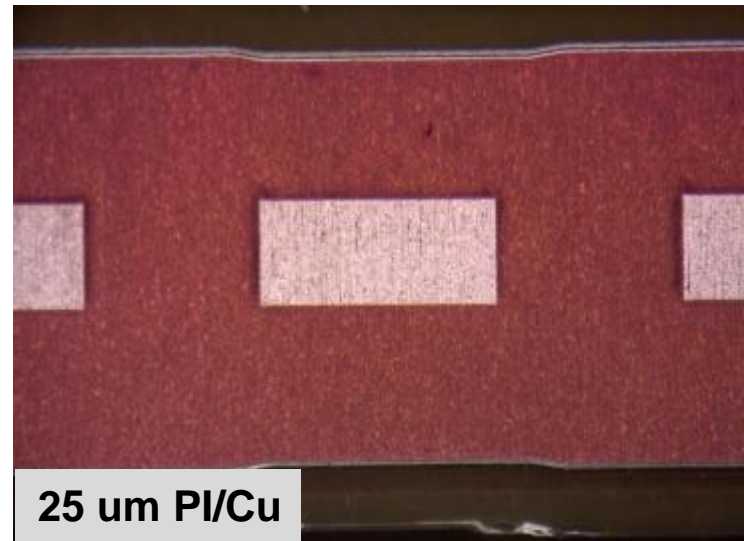
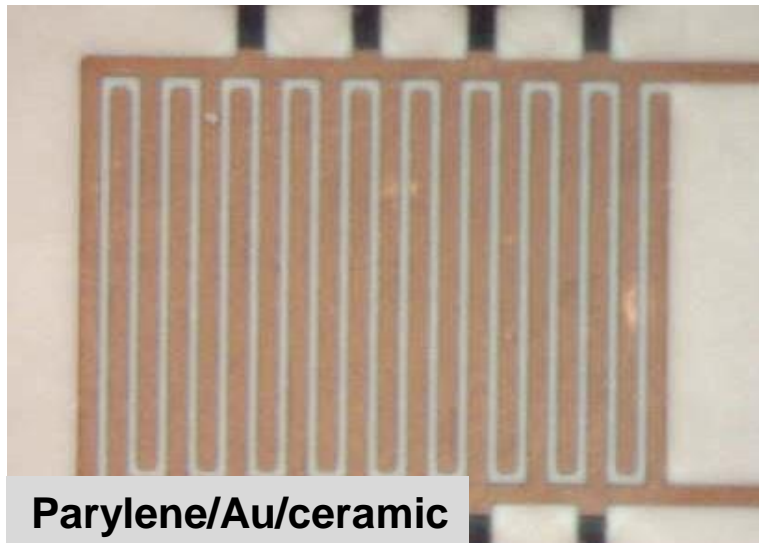
Wire-Stripping – High Resolution



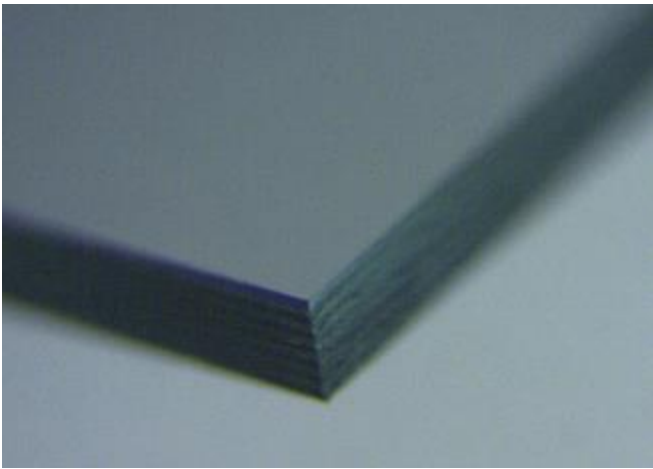
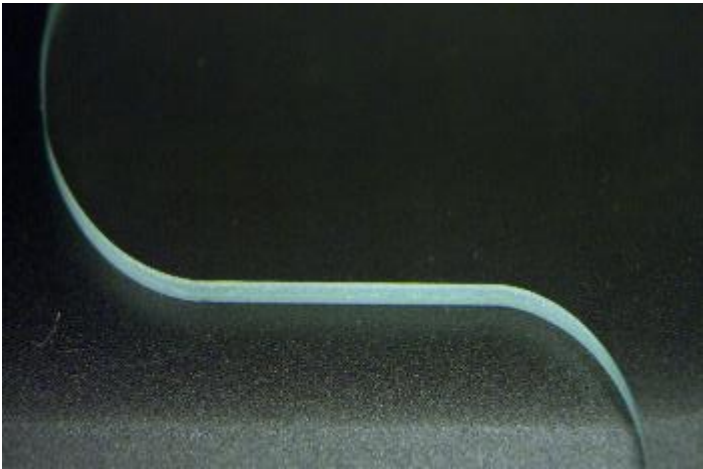
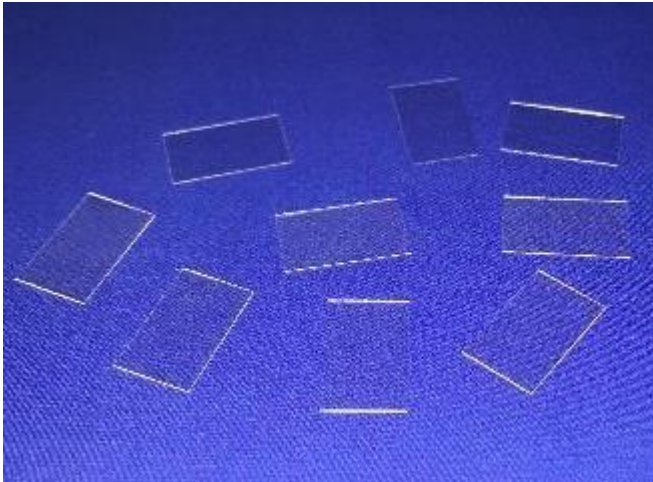
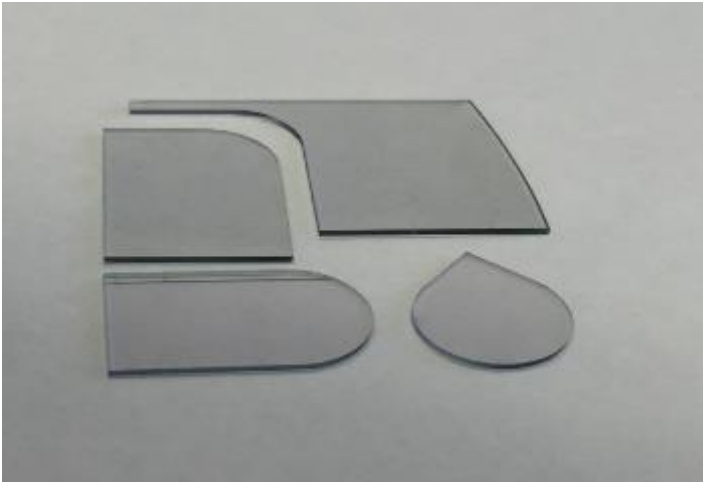
Wire Stripping - Examples



Electrode Exposure

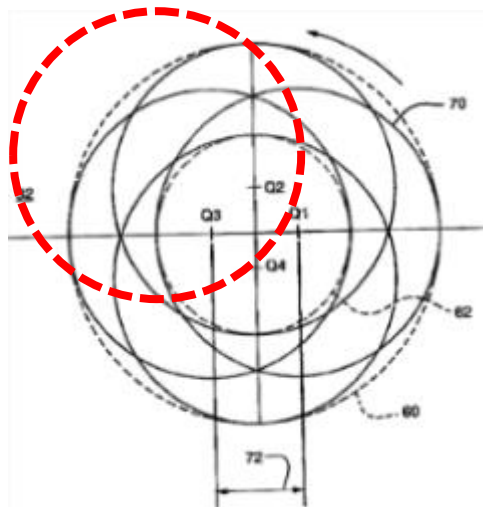
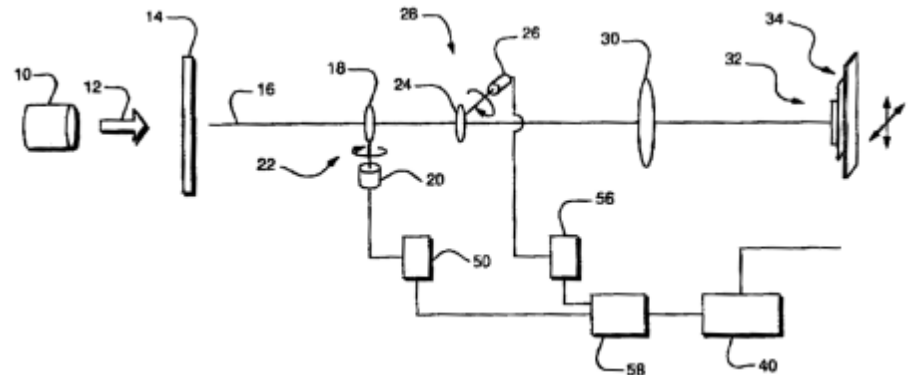
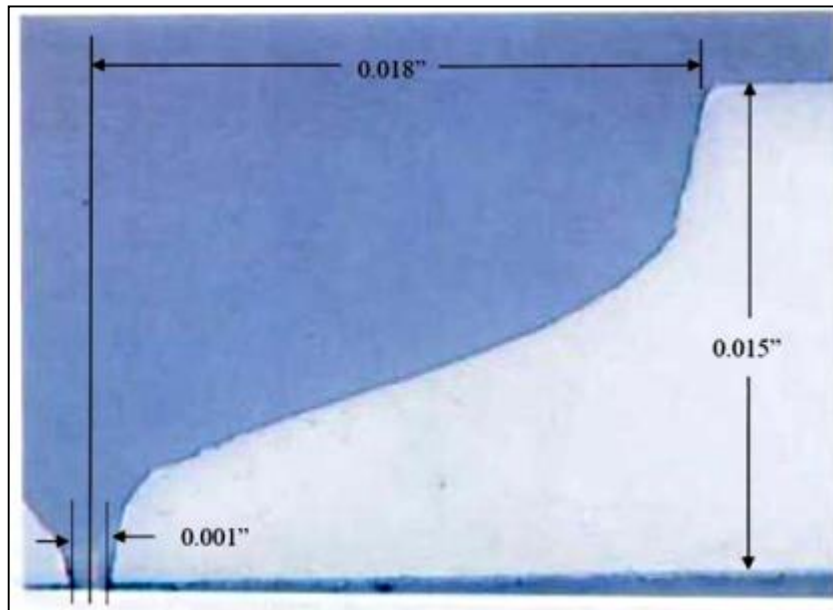


Zero-Kerf Glass Cutting



Application: 3D Ablation

Image Trepanning for Taper Control



(12) United States Patent Bernstein et al.

(10) Patent No.: **US 6,501,045 B1**
(45) Date of Patent: **Dec. 31, 2002**

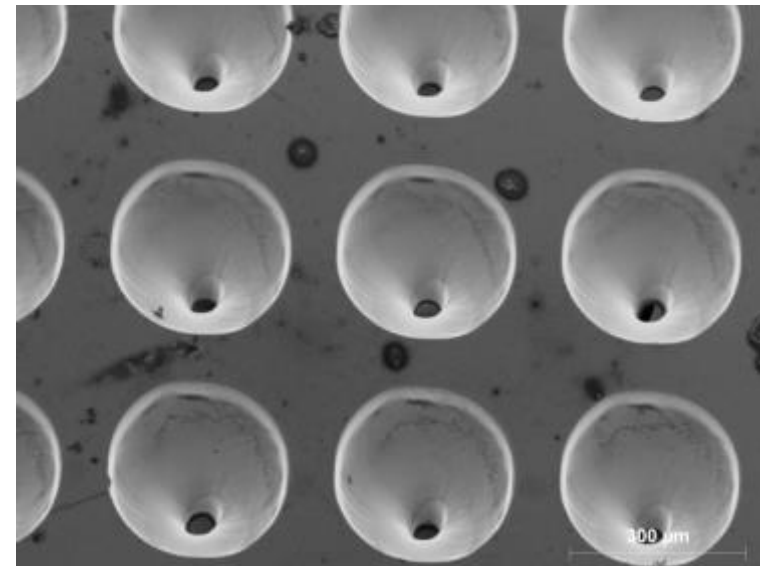
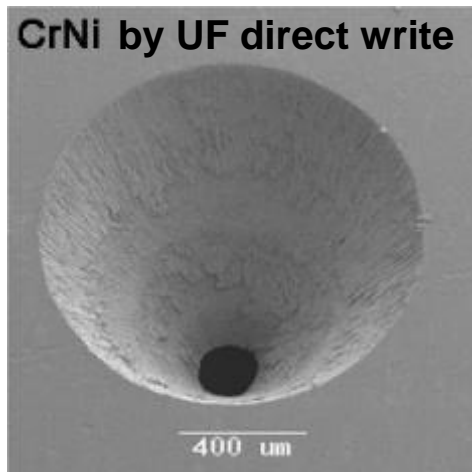
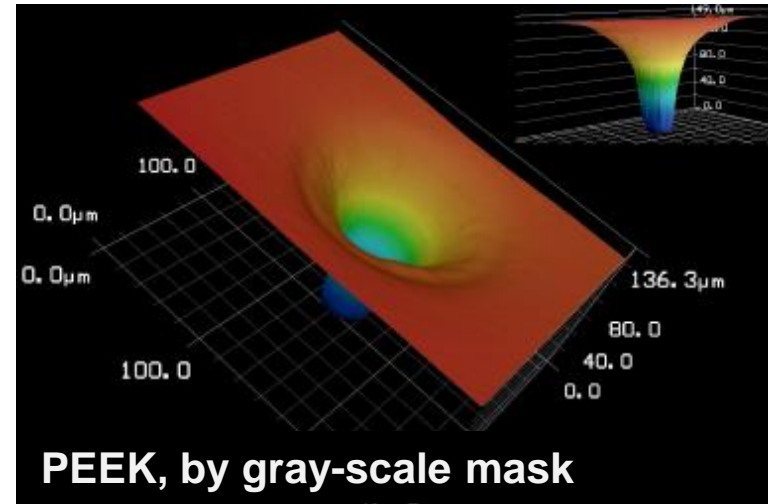
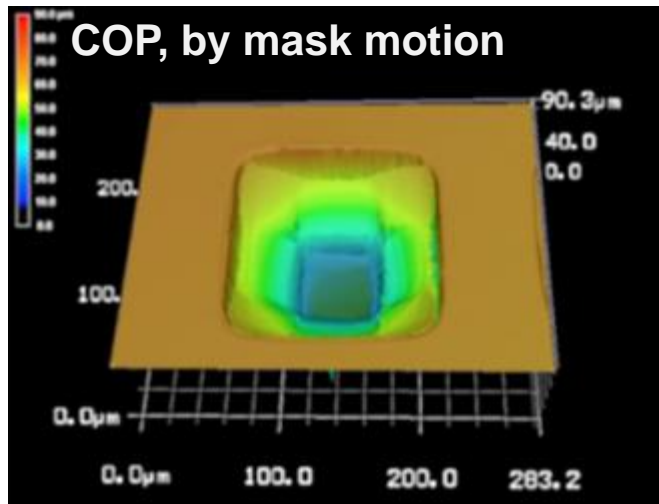
(54) METHOD AND APPARATUS FOR CONTROLLING THE TAPER ANGLE OF THE WALLS OF LASER MACHINED FEATURES

(75) Inventors: **Jeffrey Bernstein; Pascal Miller**, both of Nashua, NH (US); **Hideyuki Morishita**, Yorikaichi (JP)

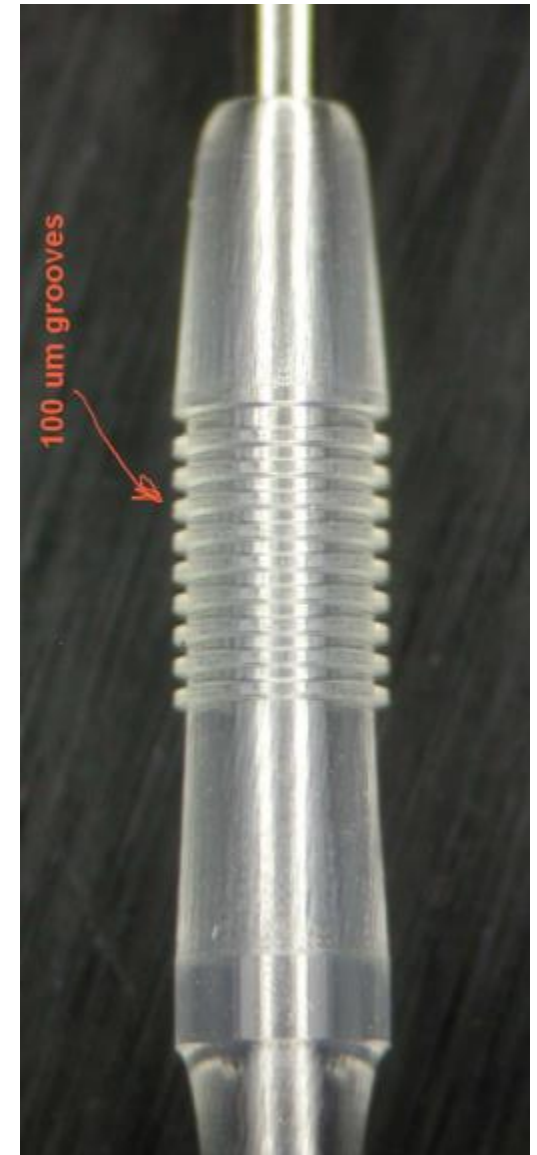
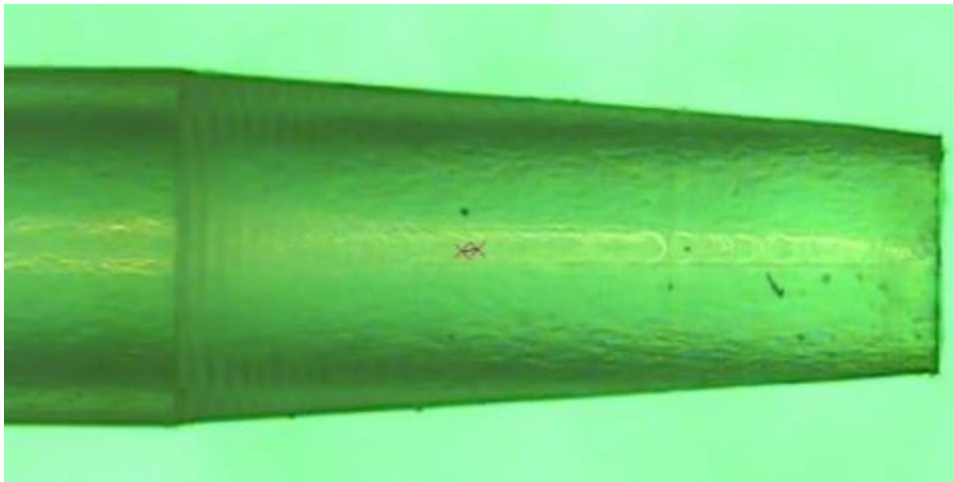
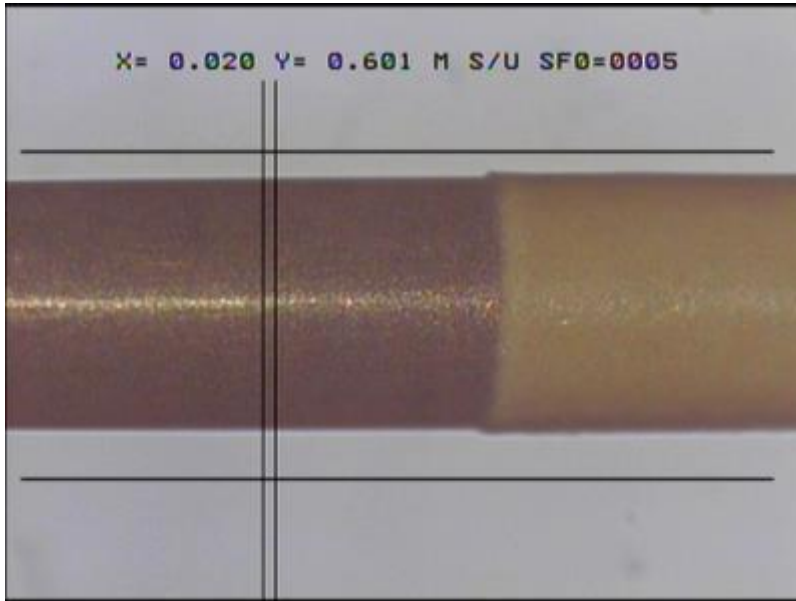
(73) Assignees: **Resonetics, Inc.**, Nashua, NH (US); **Kawamura Sangyo Co., Ltd.** (JP)

| | | | |
|-------------|-----------|-------------------|------|
| 5,043,553 A | 8/1991 | Corfe et al. | |
| 5,189,437 A | 2/1993 | Michaelis et al. | 2/45 |
| 5,213,876 A | * 5/1993 | Smyth, Jr. et al. | |
| 5,223,692 A | * 6/1993 | Lozier et al. | |
| 5,284,478 A | 2/1994 | Hanna et al. | 5/6 |
| 5,539,175 A | * 7/1996 | Smith et al. | |
| 5,550,346 A | * 8/1996 | Aadriash et al. | |
| 5,609,778 A | 3/1997 | Pulaski et al. | 26/6 |
| 5,609,779 A | 3/1997 | Crow et al. | 26/8 |
| 5,688,418 A | 11/1997 | Yoshiyasu et al. | |
| 5,800,424 A | 9/1998 | Sumiya | 5/6 |
| 5,837,964 A | 11/1998 | Emera et al. | 26/8 |
| 5,841,099 A | * 11/1998 | Owen et al. | |

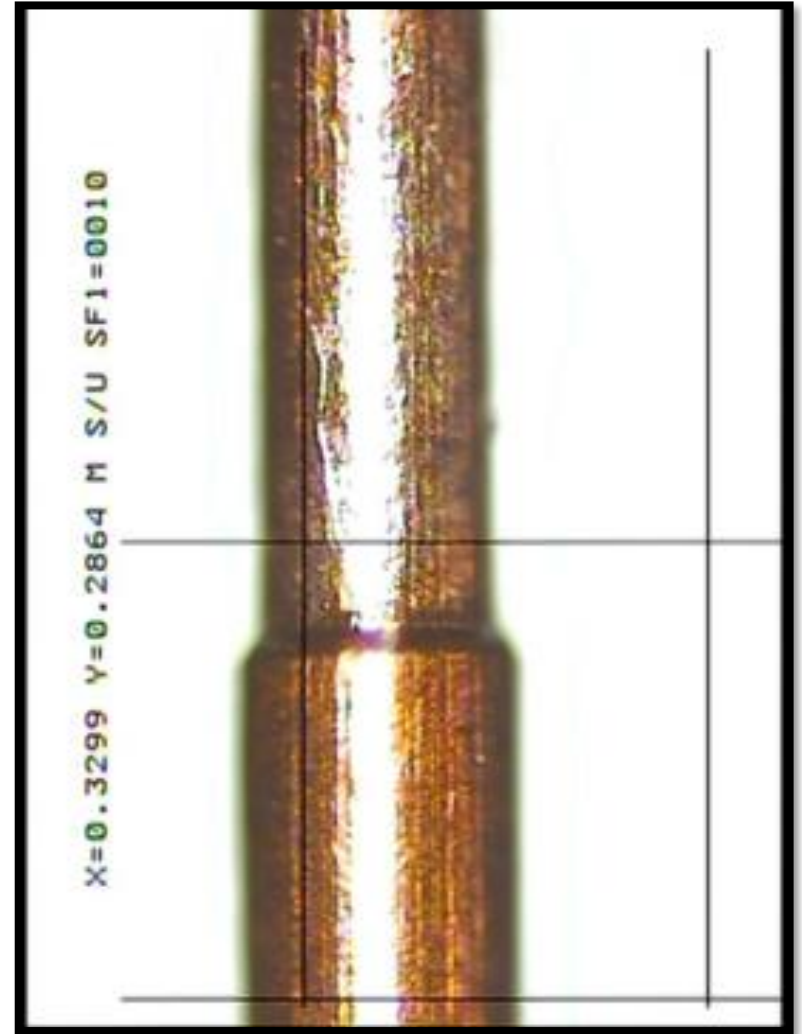
Tailored Profiles



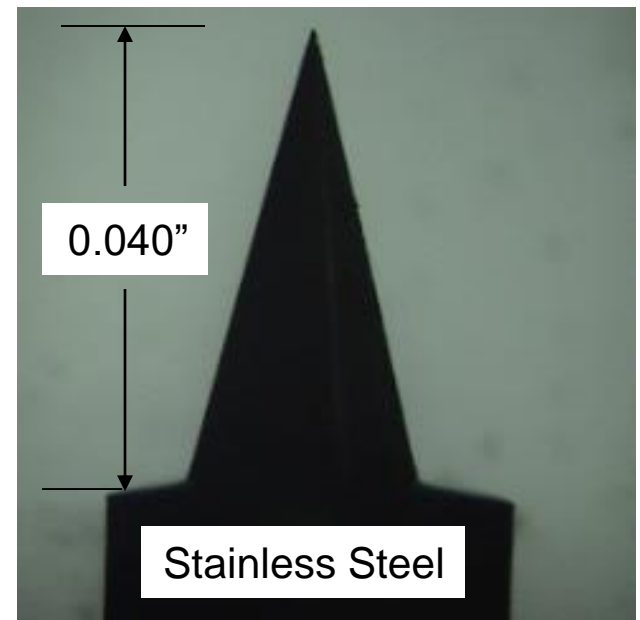
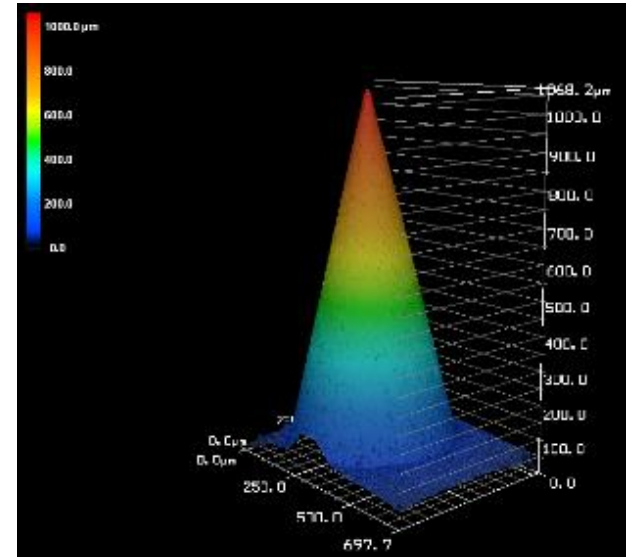
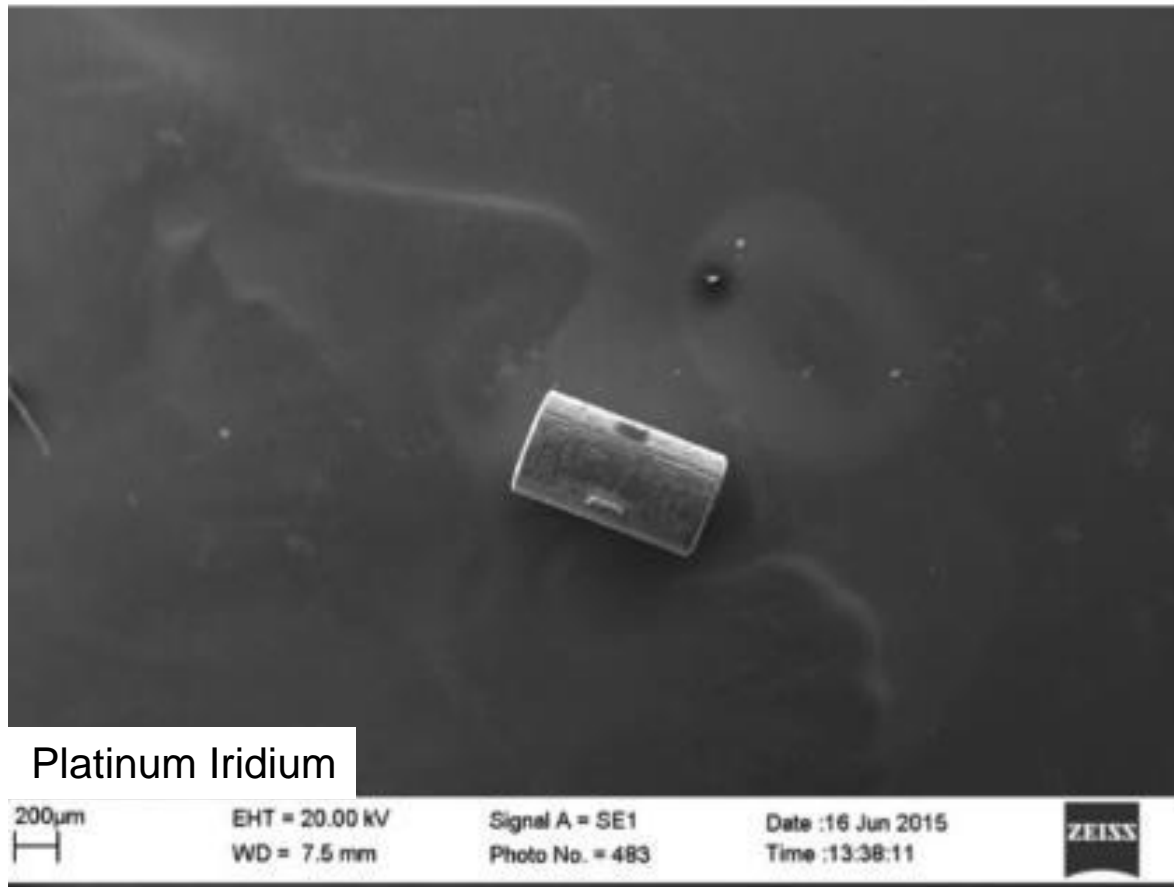
Tube Lathe – Polyimide, Pebax



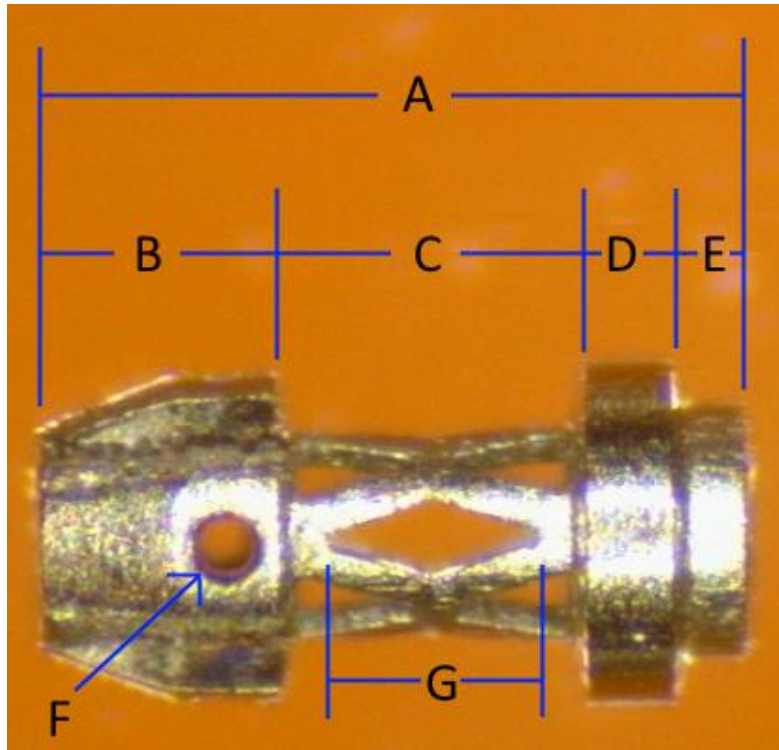
Tube Lathe - Polyimide



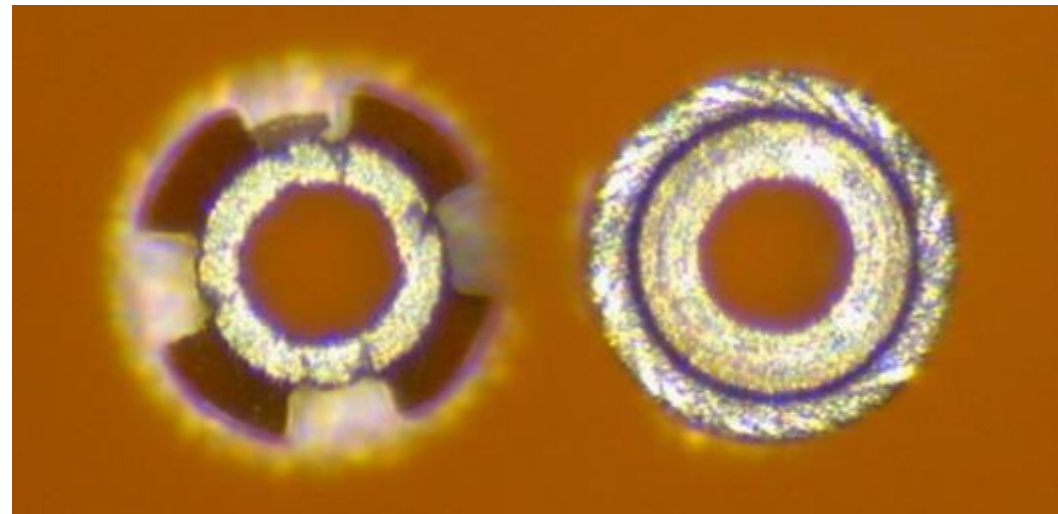
Metals: Platinum, Nitinol, Stainless Steel



Nitinol 3D Micromachining/Ablation



- Nitinol Hypotube
- ID 0.0054" (0.137mm) / OD 0.0135" (0.343mm)
- Dim A = 0.68mm
- Dim B = 0.23mm
- Dim C = 0.29mm
- Dim D = 0.095mm
- Dim E = 0.065mm
- Dim G = 0.20mm
- \varnothing C = 0.2mm
- \varnothing D = 0.343mm
- \varnothing E = 0.254mm
- \varnothing F = 0.06mm
- Tip Taper = 20°

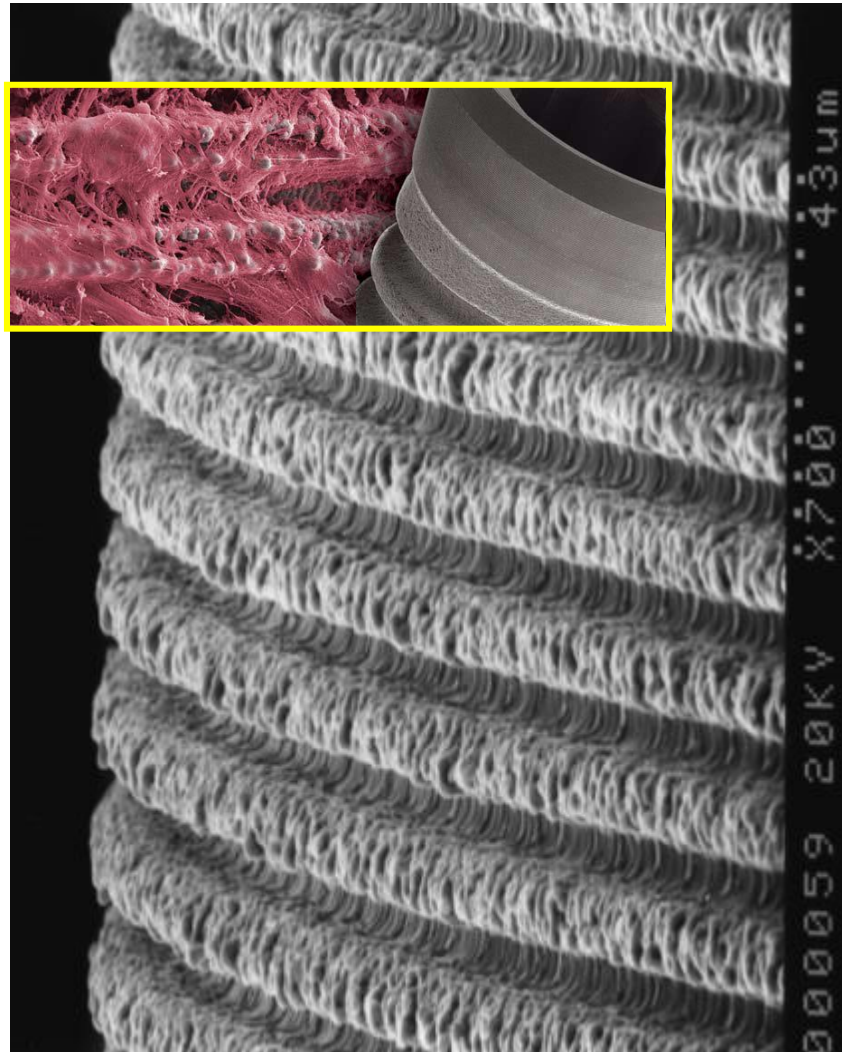


On a Dime for Scale

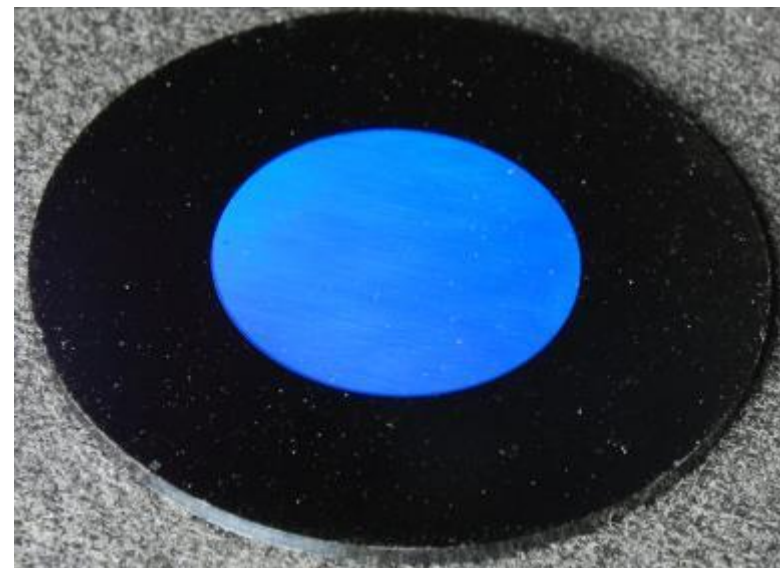
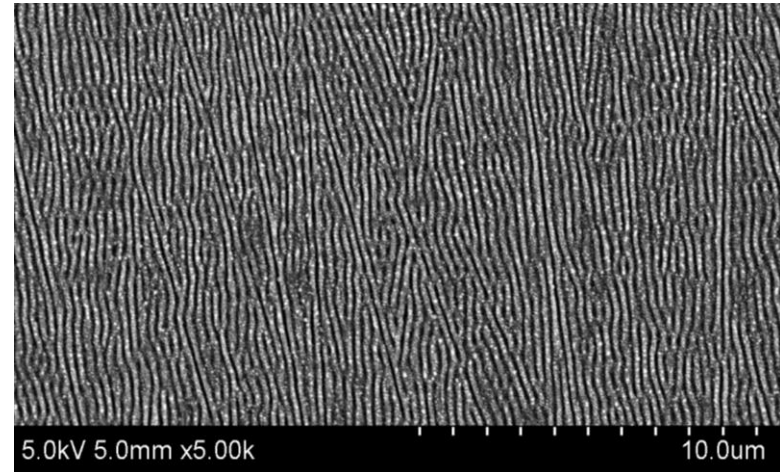


Application: Surface Texture

Surface Texturing – Micron to Nano Scale

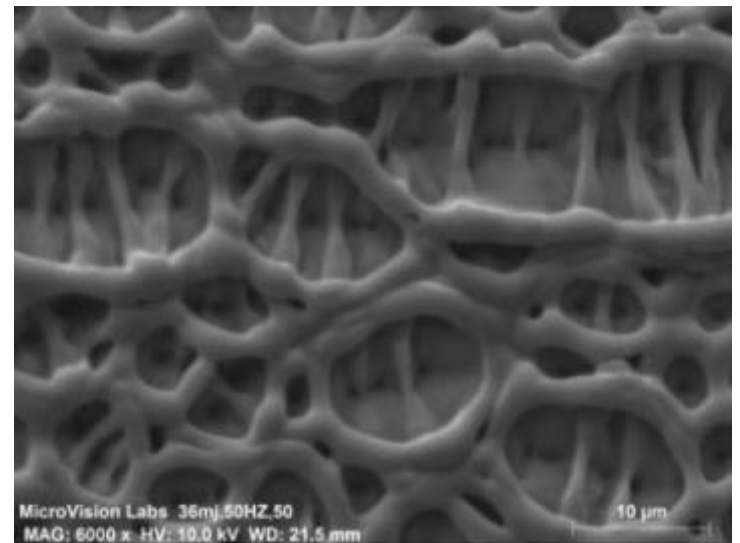
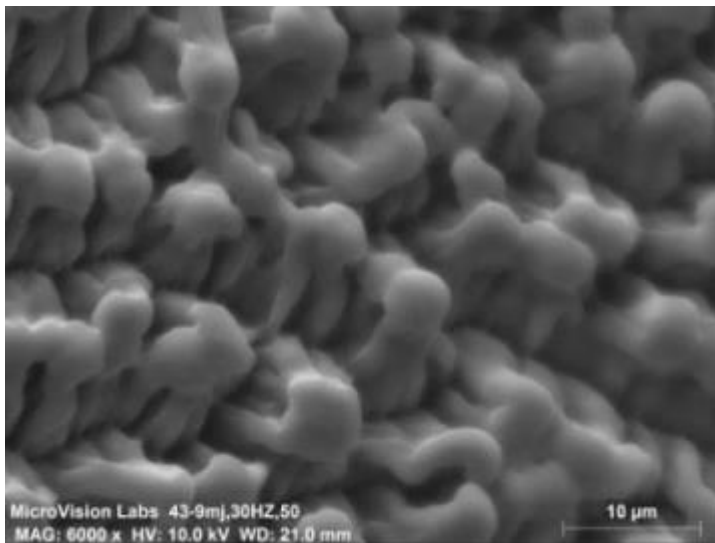
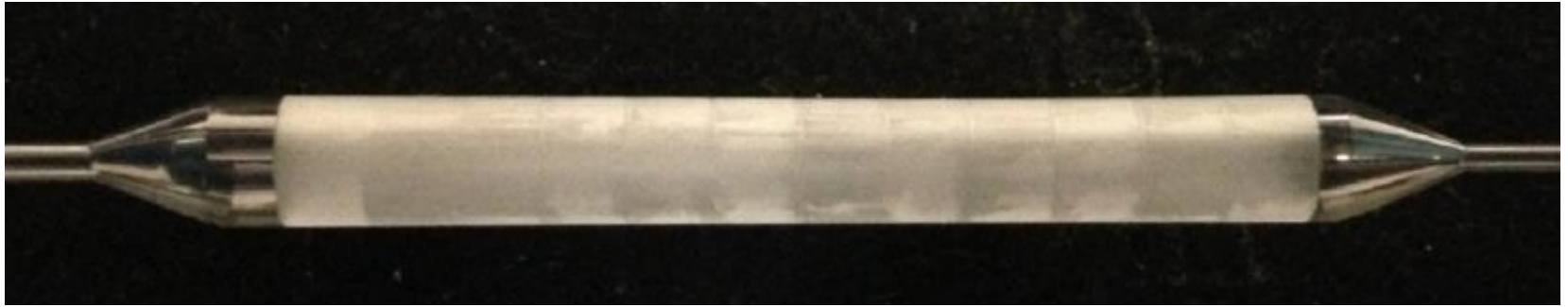


Titanium

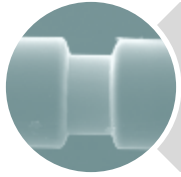


Silicon Carbide

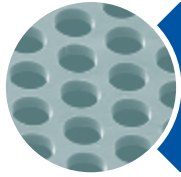
(Balloon) Surface Texturing



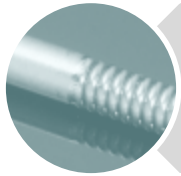
Technologies



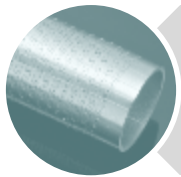
Ablating



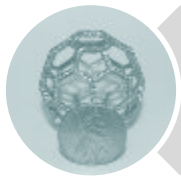
Drilling



Welding

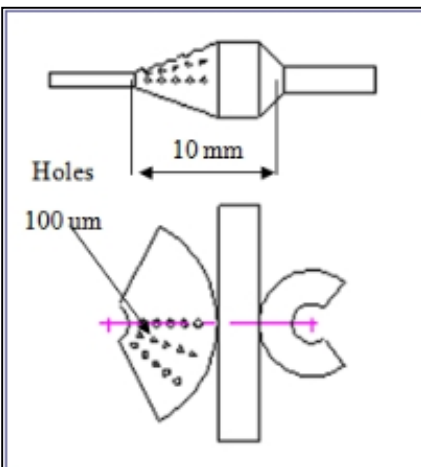
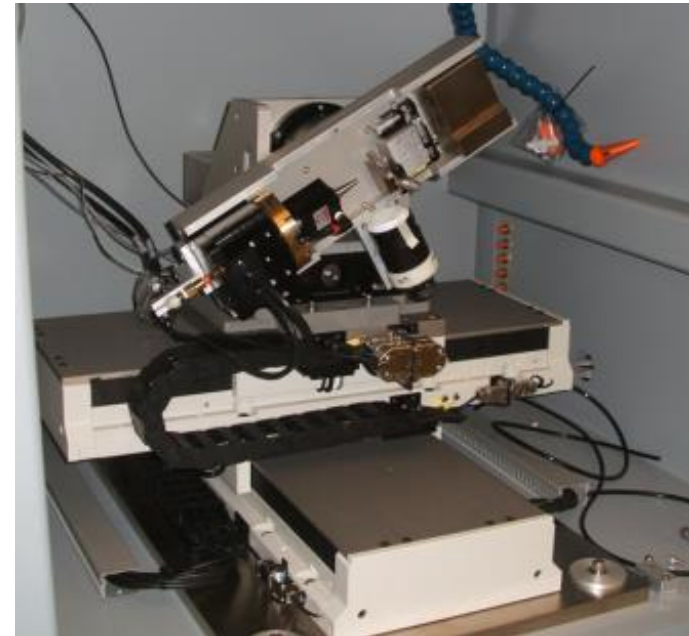
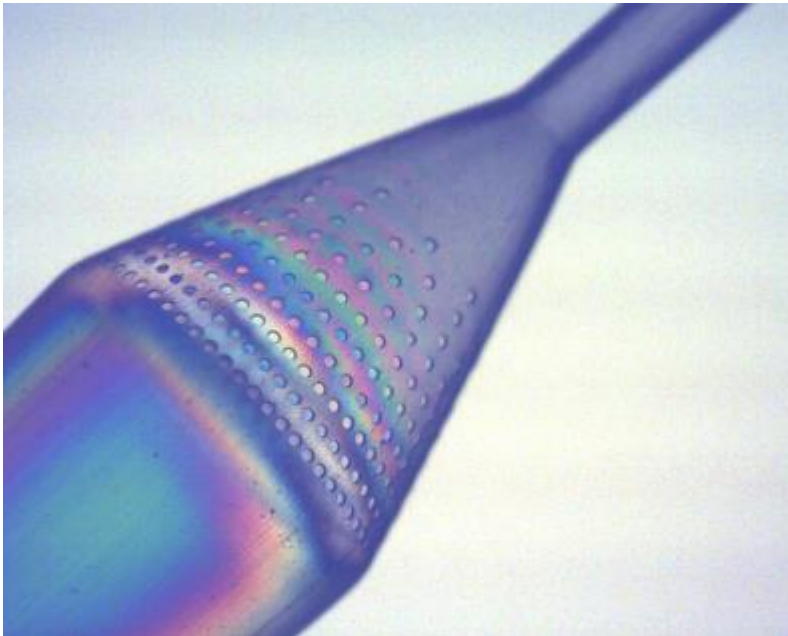


Cutting



Additive

Mask Projection Hole Drilling: Filters



(12) United States Patent Broude et al.

(10) Patent No.: **US 7,812,280 B2**
(45) Date of Patent: **Oct. 12, 2010**

(54) METHOD AND APPARATUS FOR LASER MICROMACHINING A CONICAL SURFACE

(75) Inventors: **Sergey V. Broude**, Newton Center, MA (US); **Rong Gu**, Hudson, NH (US); **David S. Holbrook**, Lexington, MA (US); **Kenneth T. McDaniel**, Merrimack, NH (US); **Pascal Miller**, Groton, MA (US); **David L. Wall**, Burlington, MA (US)

| | | | |
|-------------------|---------|----------------------|------------|
| 5,760,366 A * | 6/1998 | Haruta et al. | 219/121.68 |
| 6,008,914 A * | 12/1999 | Sasagawa et al. | 359/15 |
| 6,091,047 A * | 7/2000 | Miyakawa et al. | 219/121.68 |
| 2003/0196996 A1 * | 10/2003 | Jennings et al. | 219/121.73 |
| 2004/0223330 A1 | 11/2004 | Broude et al. | 362/268 |

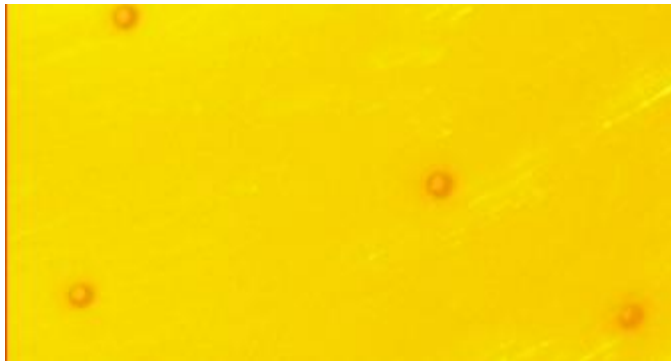
FOREIGN PATENT DOCUMENTS

| | | |
|----|--------------|---------|
| EP | 0 575 850 A2 | 12/1993 |
| JP | 2001096389 | 4/2001 |

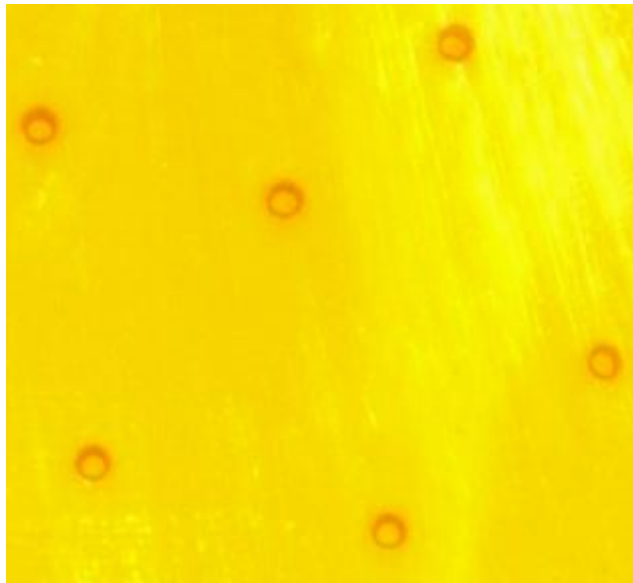
(73) Assignee: **Resonetics, Inc.**, Nashua, NH (US)

OTHER PUBLICATIONS

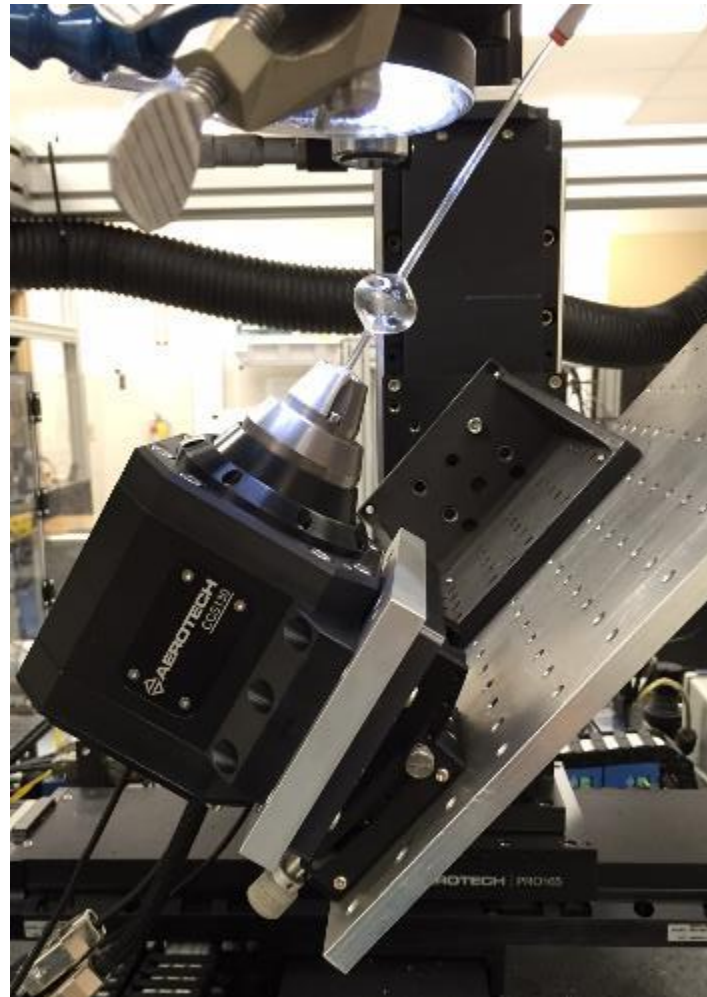
Direct Focus Hole Drilling: Balloon



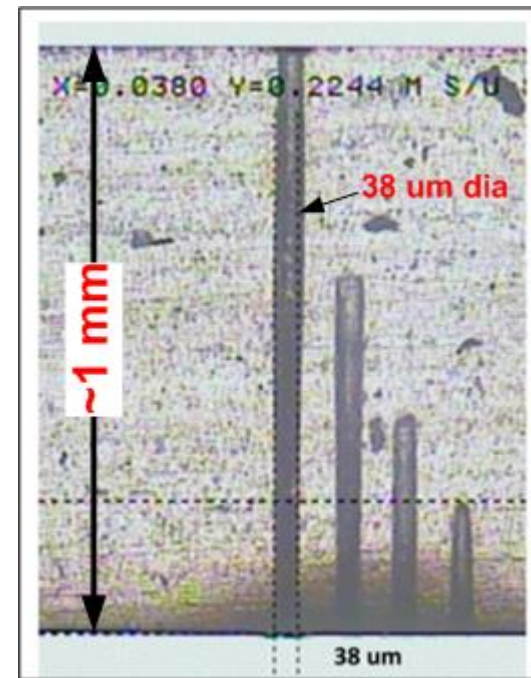
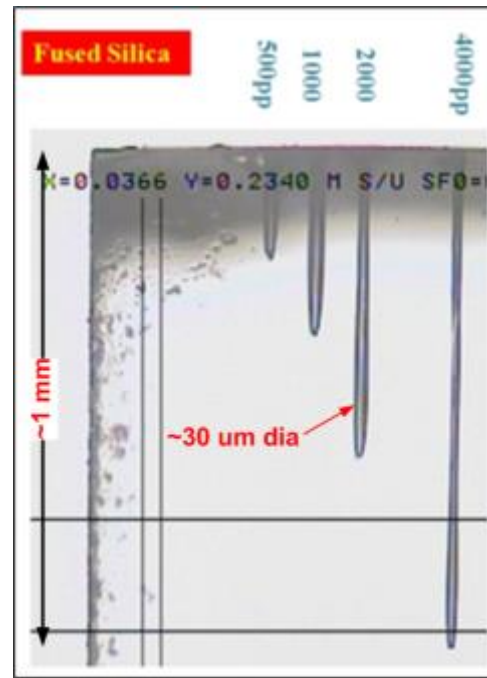
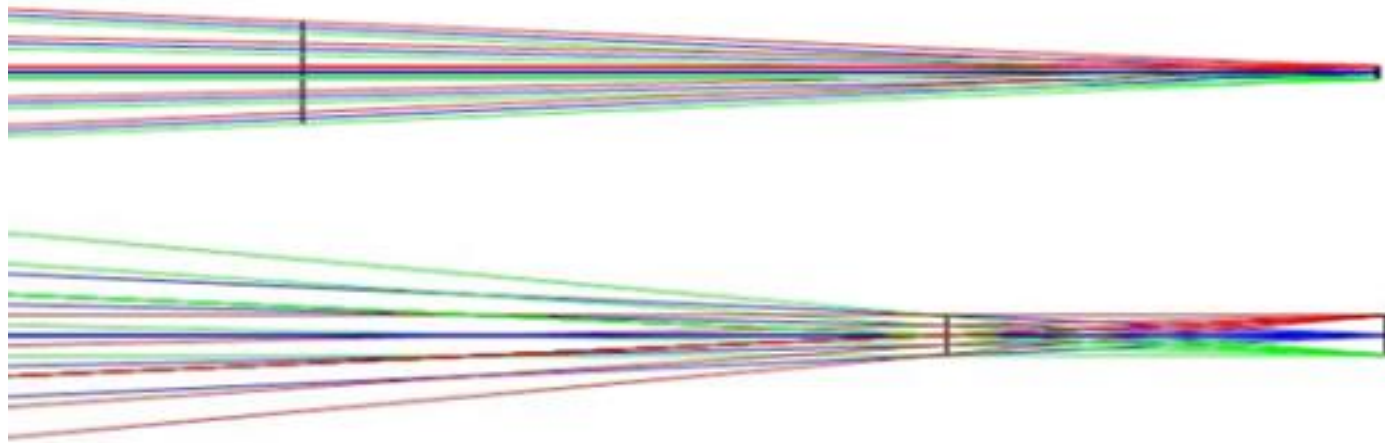
0.002" Diameter Holes



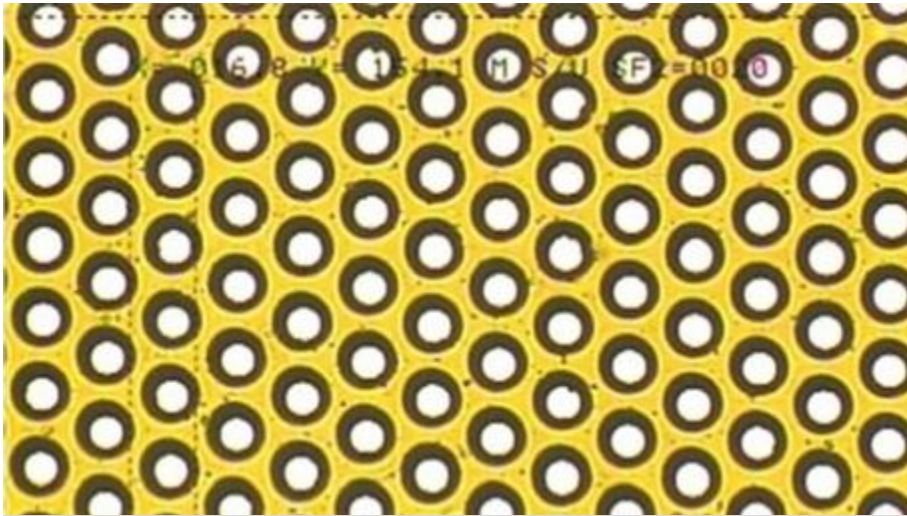
0.004" Diameter Holes



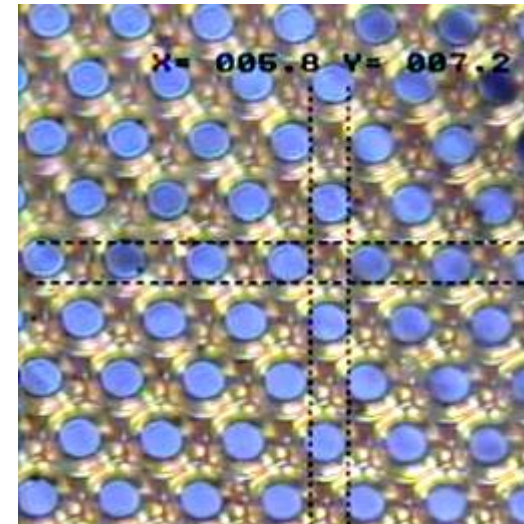
Deep Hole Drilling



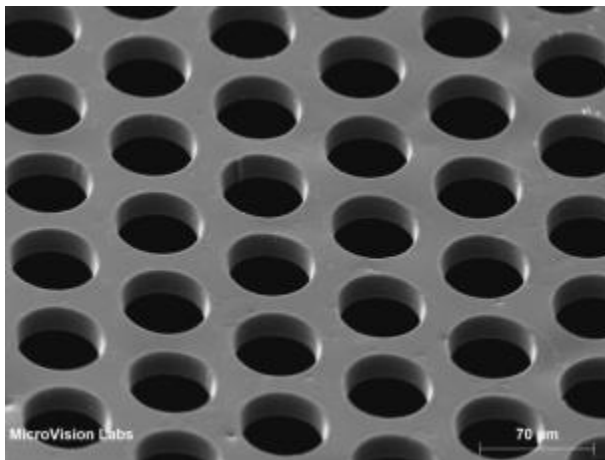
Hole Arrays



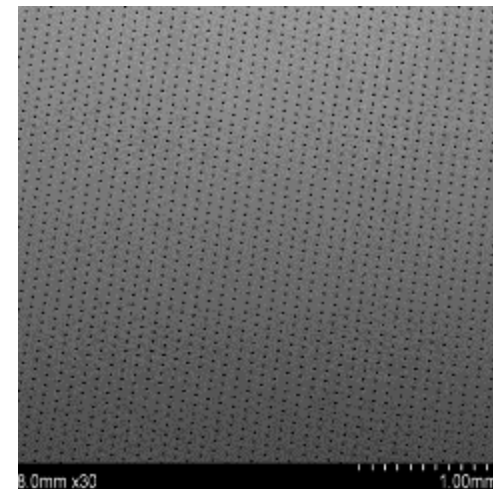
17 um dia in 50 um PET film



7 um dia in 13 um PI film

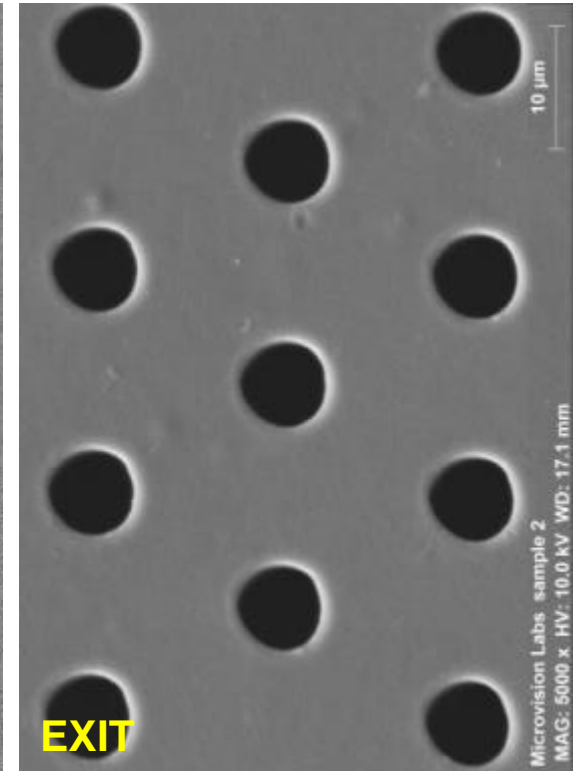
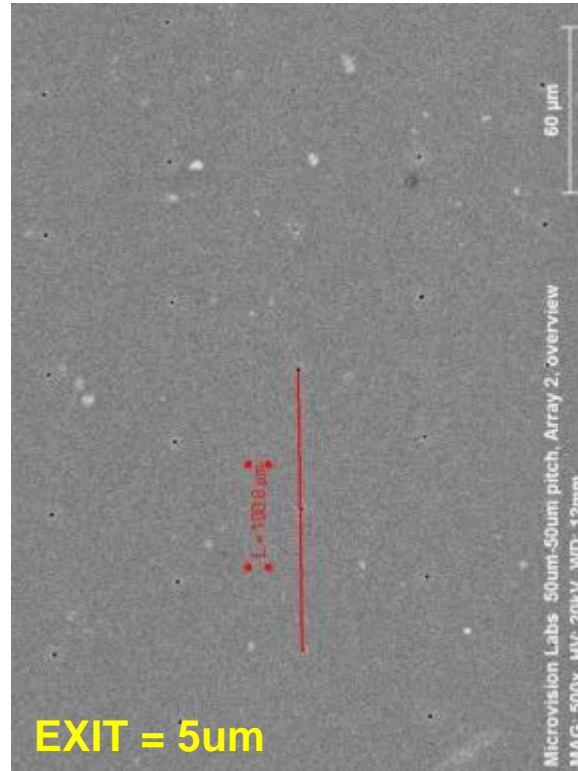
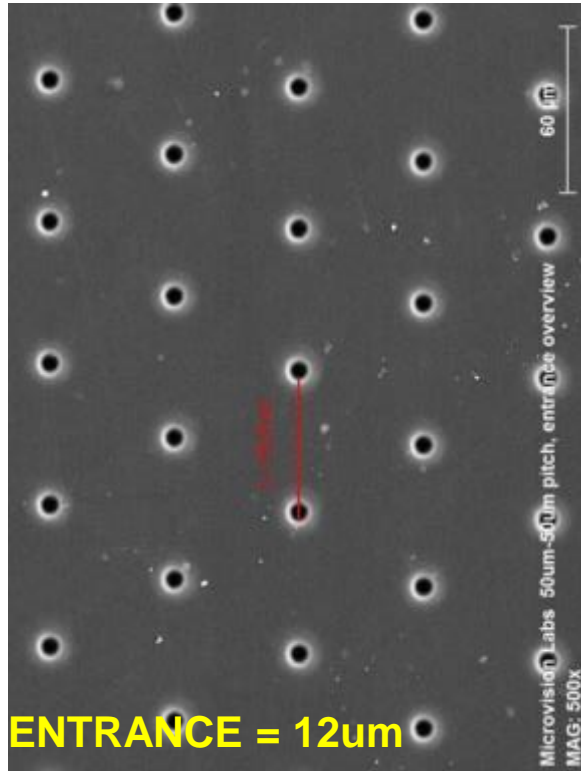


50 um dia in PU 25 um thick



20 um dia in 75 um thick SS

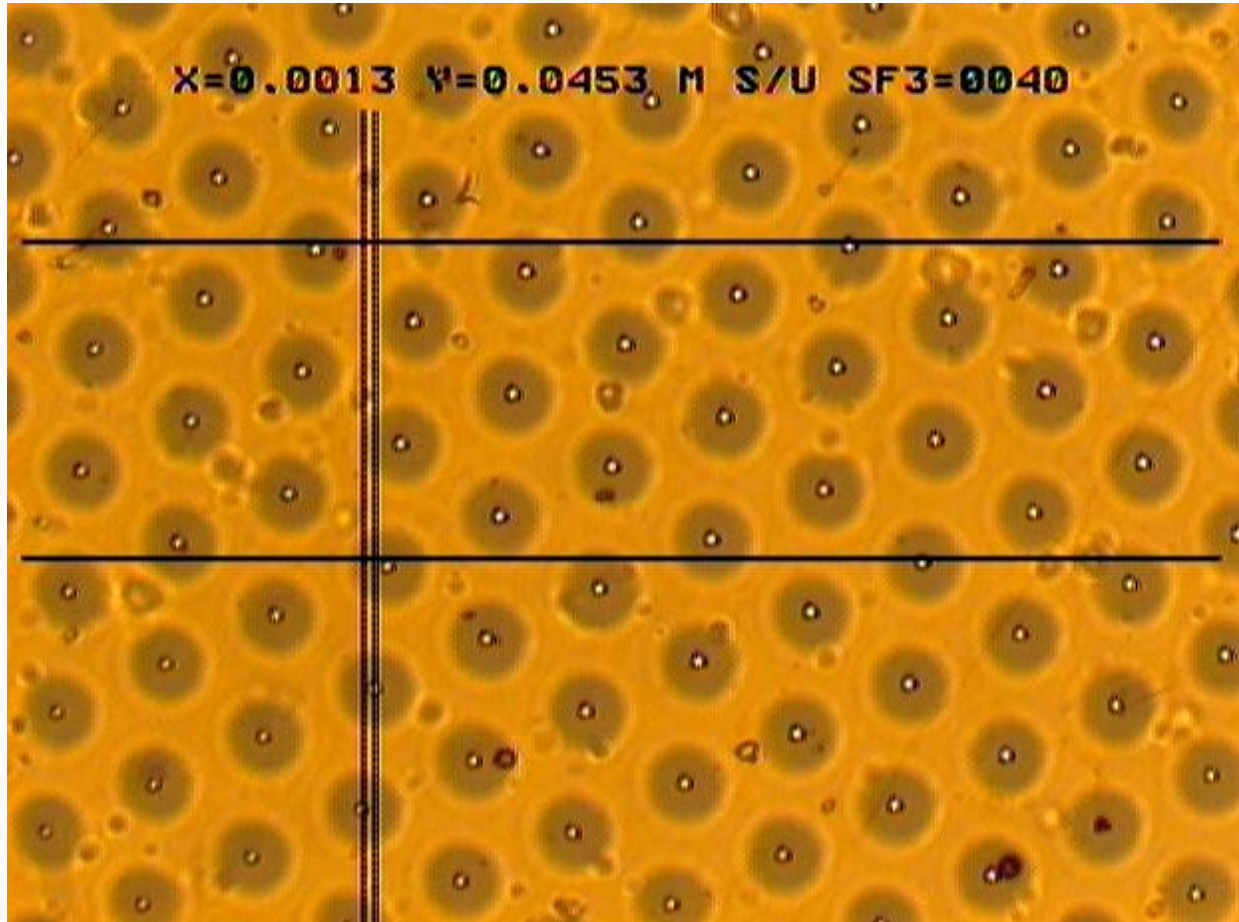
Small Holes: 25 um PI



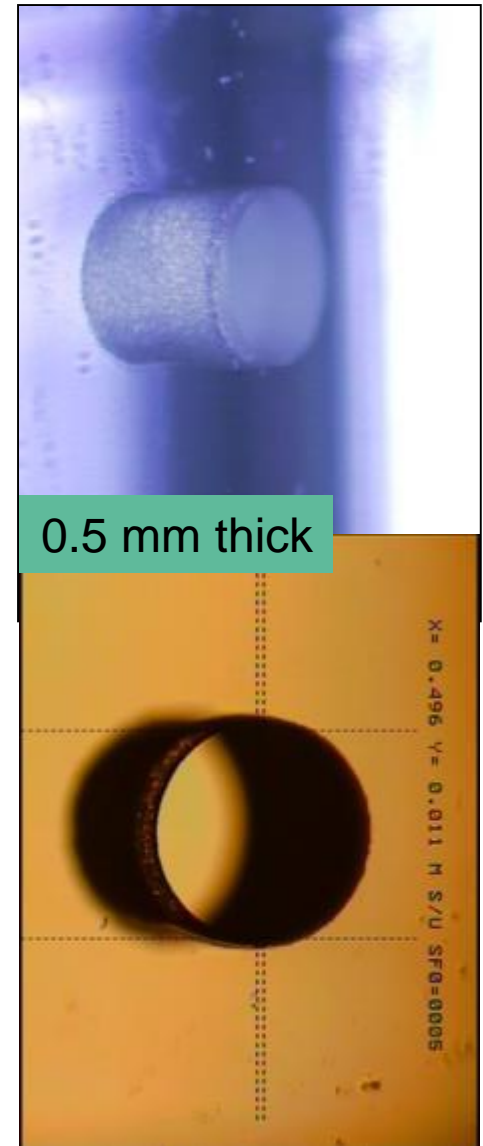
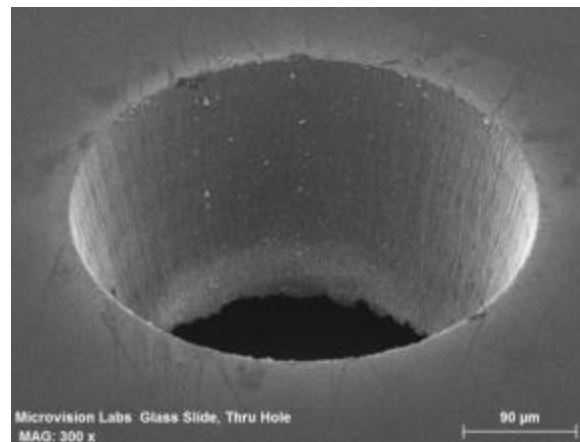
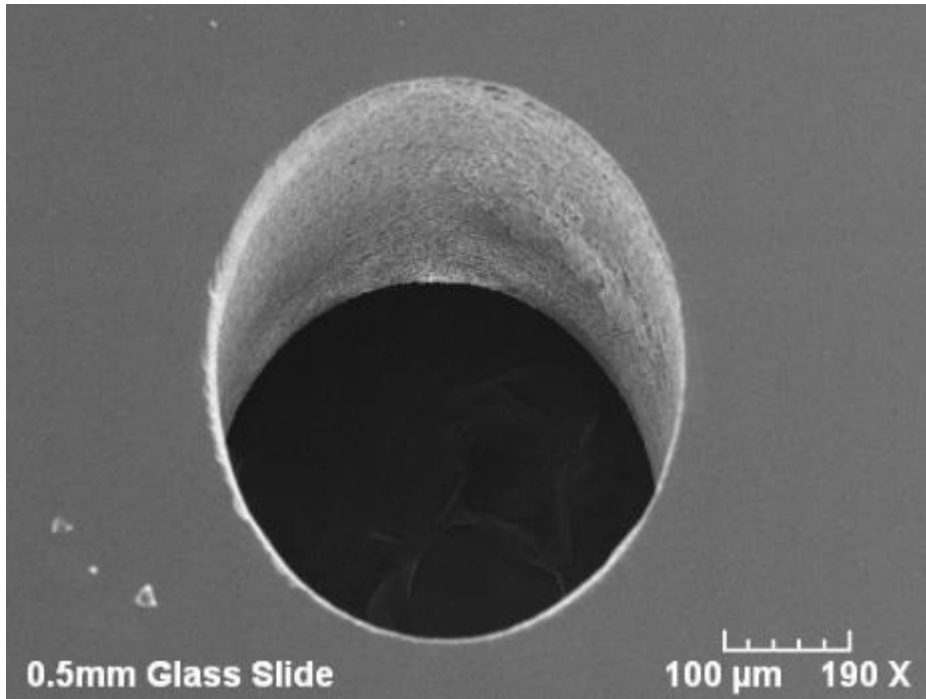
Exit dia = 5 um

Exit dia = 7 um

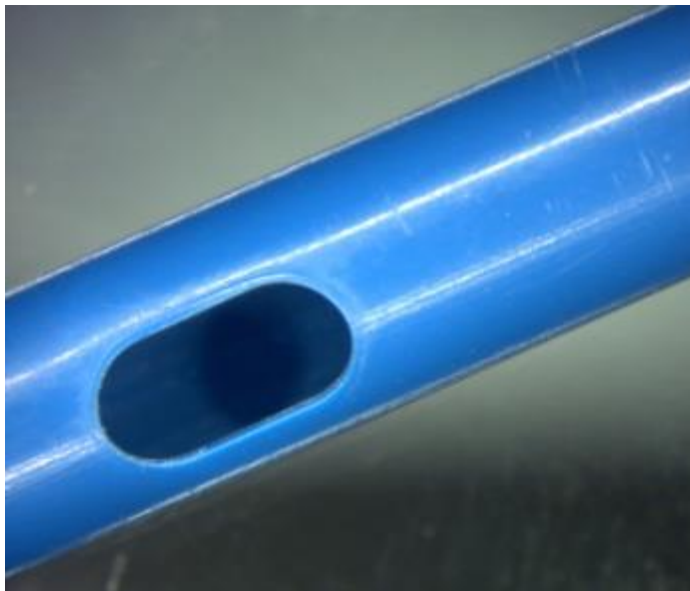
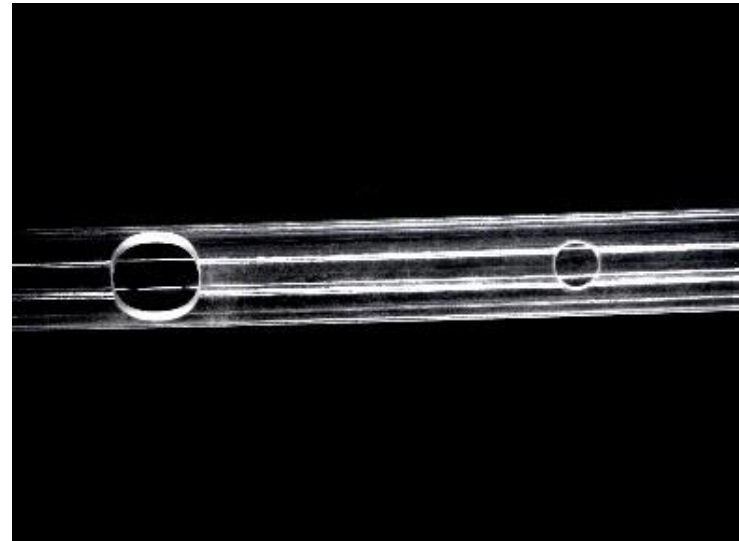
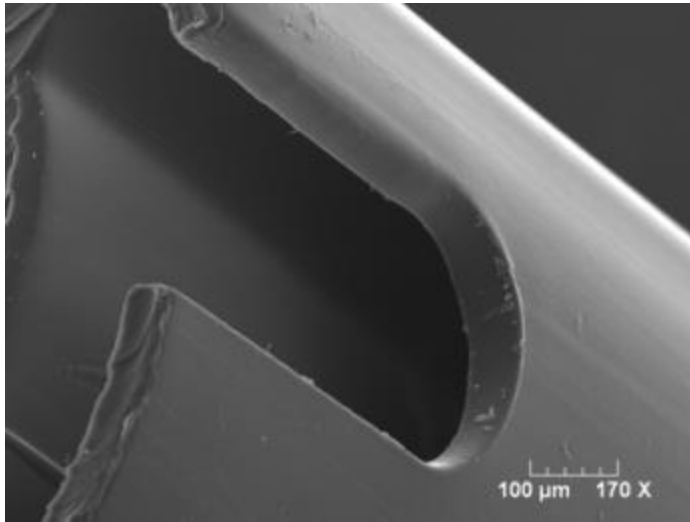
Small Holes: 1 um dia holes in 25 um PI



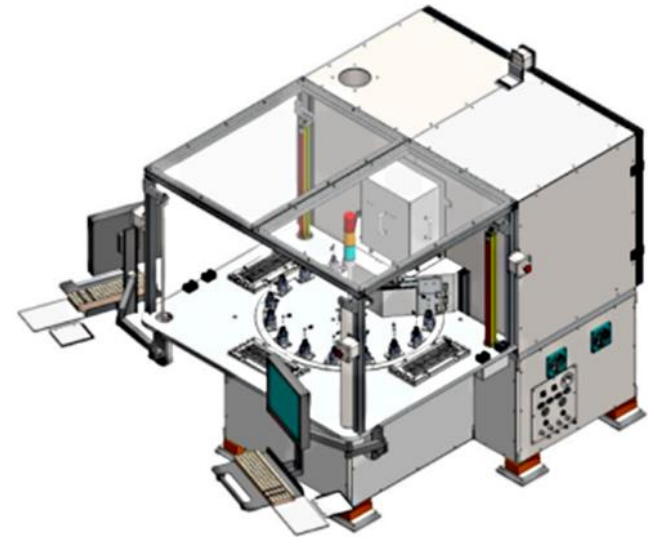
Holes in Glass



Single, Multi Lumen Tube - Drilling, Skiving



Femtosecond Drilling Workstation



US 20130193618A1

(19) **United States**

(12) **Patent Application Publication**
Miller et al.

(10) **Pub. No.:** US 2013/0193618 A1
(43) **Pub. Date:** Aug. 1, 2013

(54) **LASER MACHINING SYSTEM AND METHOD FOR MACHINING THREE-DIMENSIONAL OBJECTS FROM A PLURALITY OF DIRECTIONS**

(52) **U.S. CL.**
CPC *B29C 59/16* (2013.01)
USPC 264/400; 425/174.4; 425/150; 425/169

(75) **Inventors:** Pascal Miller, Groton, MA (US);
Sergey Broude, Newton Center, MA (US);
David L. Wall, Burlington, MA (US);
Kenneth Todd McDaniel, Merrimack, NH (US)

(57) **ABSTRACT**

Embodiments of the present disclosure are directed to systems (300), devices and methods for machining a work-piece from a plurality of directions using a single laser beam and galvanometer scan head (302). In some embodiments, such a system includes, for example, a scanning galvanometer head ("scan-head") (302), having one or more mirrors (323) for directing a laser beam in at least one plane. Preferably, in some embodiments, the scan-head includes two mirrors for deflecting the laser beam in the at least one plane (e.g., an X-Y plane). A plurality of second mirrors (312A, 312B, 312C) is arranged after the scan-head (302) to direct the laser onto a

(73) **Assignee:** RESONETICS LLC, Nashua, NH (US)

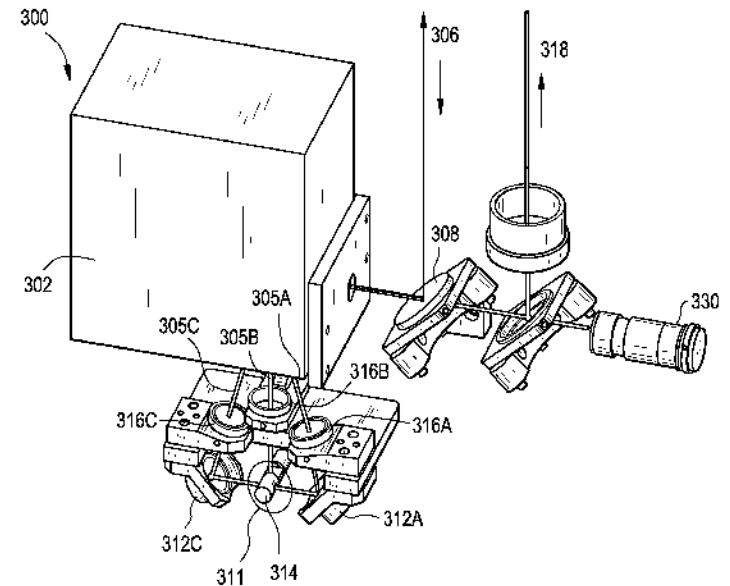
(21) **Appl. No.:** 13/520,089

(22) **PCT Filed:** Dec. 30, 2010

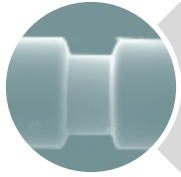
(86) **PCT No.:** PCT/US10/62498

§ 371 (c)(1),

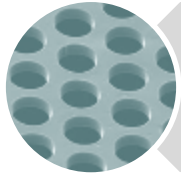
(2), (4) **Date:** Sep. 24, 2012



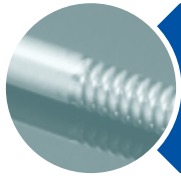
Technologies



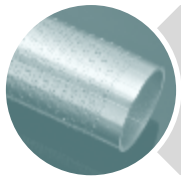
Ablating



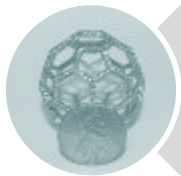
Drilling



Welding



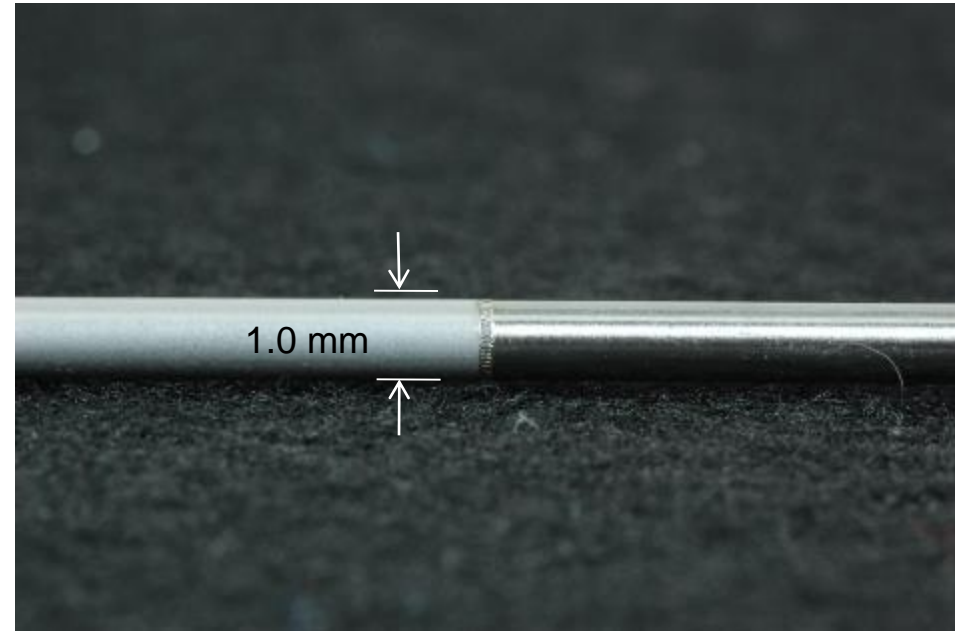
Cutting



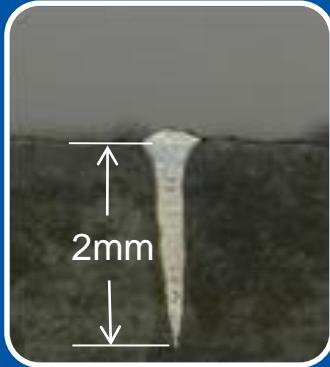
Additive

Why Use Laser Welding?

- Parts Requirements:
 - Structural strength
 - Up to 80% of base material
 - Hermetic (gas tight)
 - Down to 1×10^{-9} cc/sec He
 - Cosmetic
 - No post process finishing
 - Size
 - Features
 - 1mm to 0.075mm
 - Low heat input

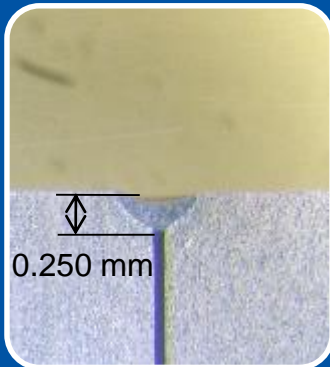


Types Of Laser Welding



Keyhole

- Power Density $>10^6$ W/cm²
- Depth : Width Ratio $> 3:1$
- High Speed – Fiber Laser – up to 1 meter/second
- Typical - CW Solid State, CO₂

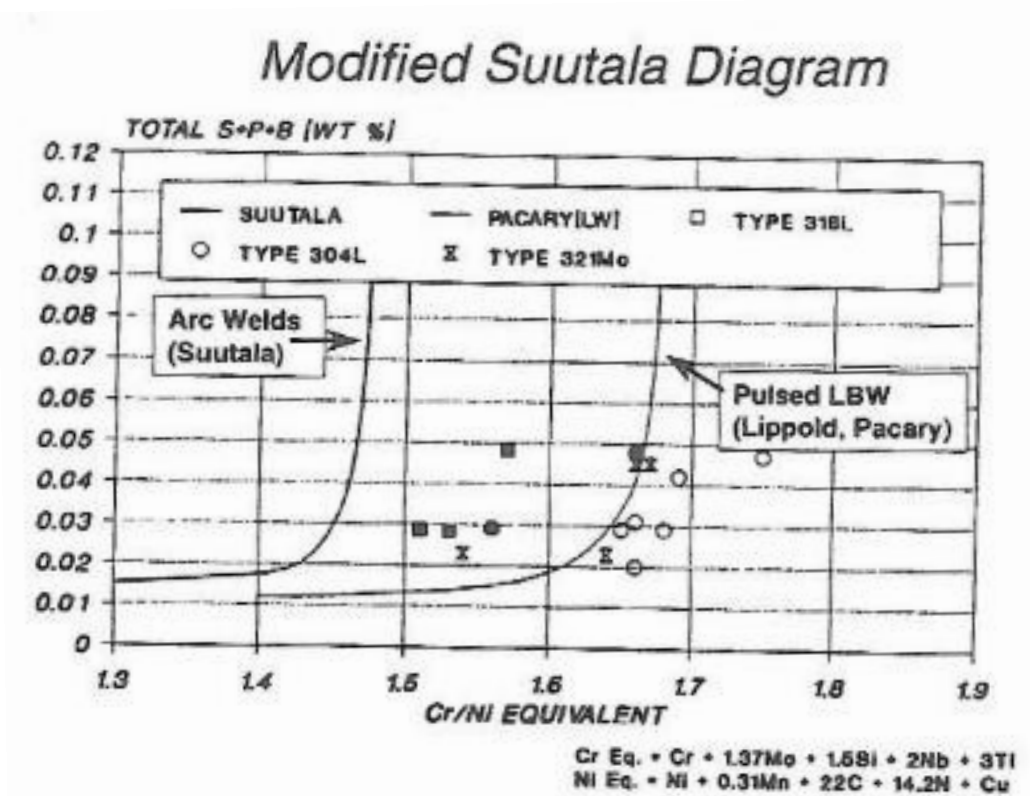


Conduction

- Power Density $<10^6$ W/cm²
- Depth : Width ratio $< 3:1$
- Typical - Pulsed Nd:YAG, fiber laser

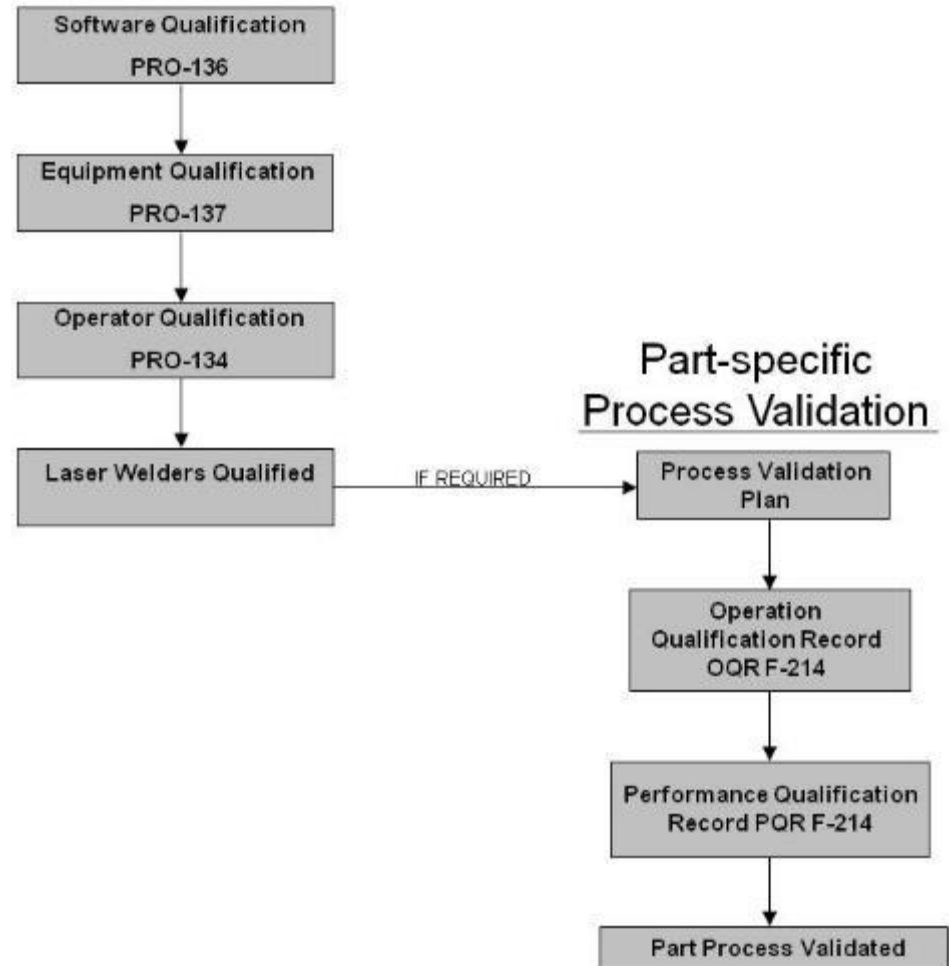
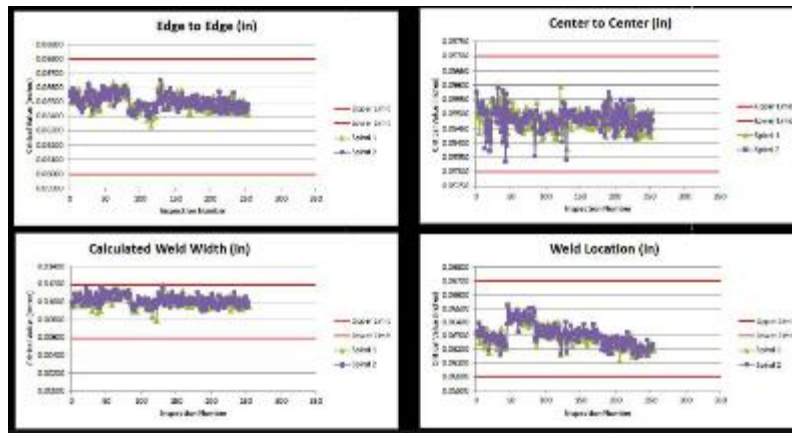
Laser Weldable Metals

- Stainless Steel
 - Problem Elements – Sulfur, Oxygen, Carbon
- Titanium, Titanium Alloys
- Nitinol – nickel rich
- Cobalt Chrome
- Copper, Nickel
- Gold, Platinum, Silver
- Nickel-Based Alloys
- Some Aluminum



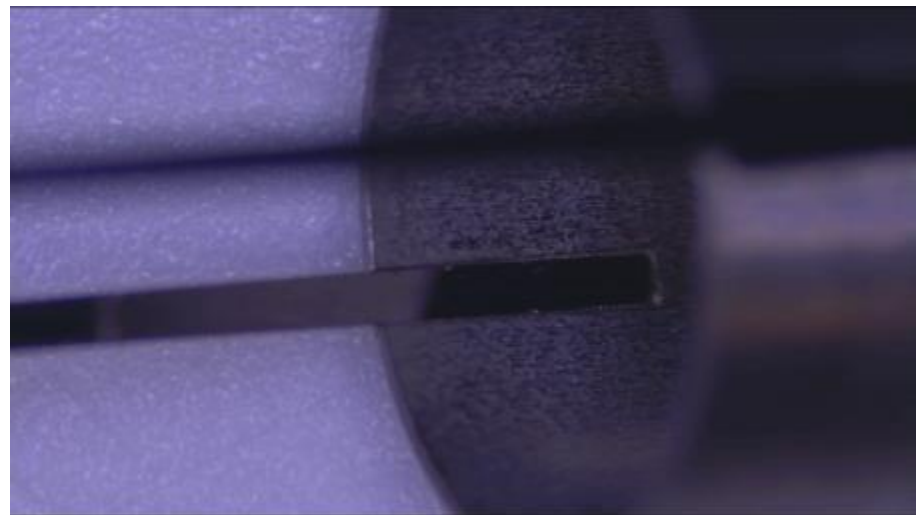
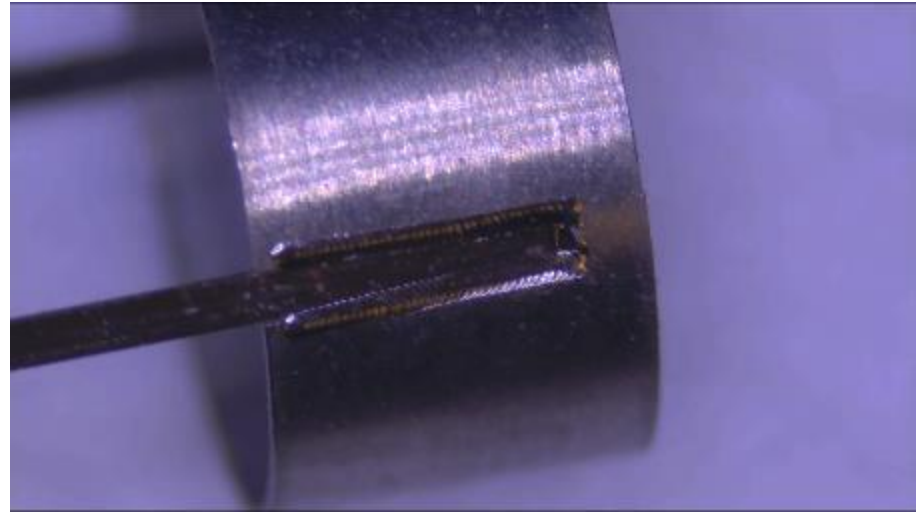
Process Validation

- OEM approved validation protocol
 - Feasibility
 - Engineering Study
 - Validation
- Process capability driven



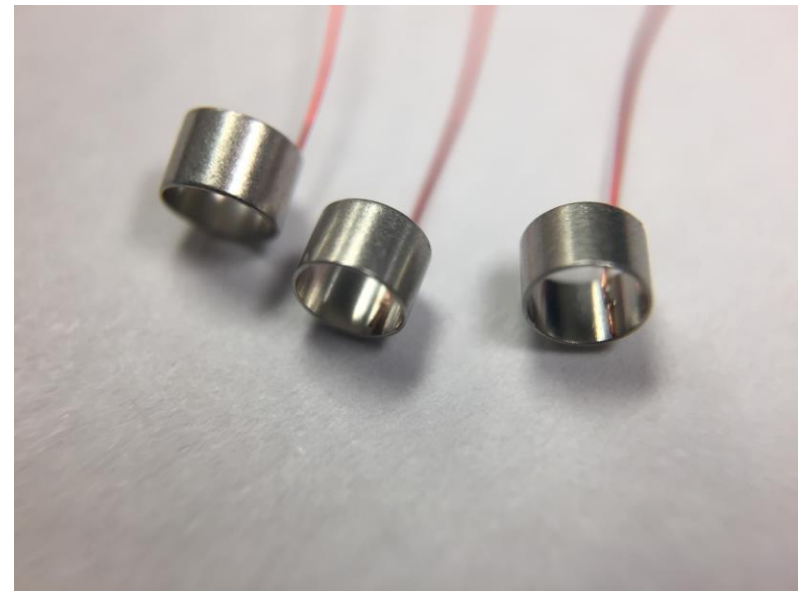
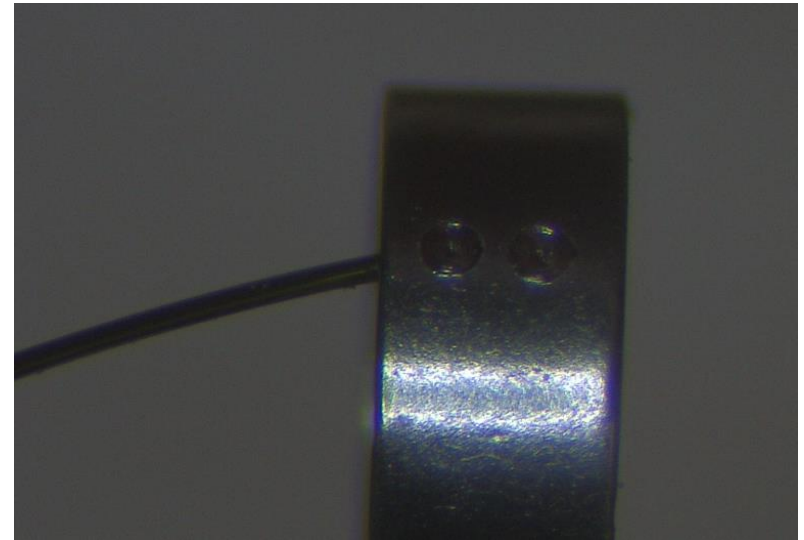
Pull Ring Welding

- Stainless Steel
- Laser cut pull ring
- 15 lbs. + pull strength
- Semi-automated system in development



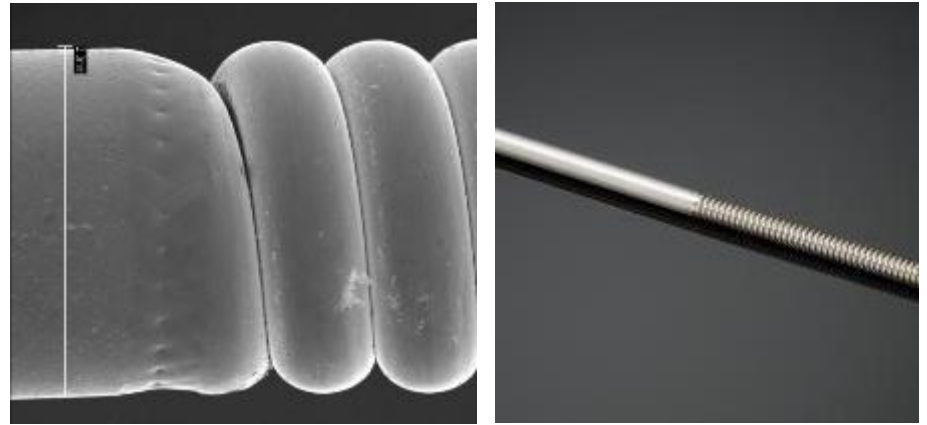
Wire Stripping, Electrode Welding

- Platinum/Iridium, Stainless Steel electrodes
- Wire stripping
 - 0.003" diameter nickel wire
- Laser weld assembly
- Semi-automated, automated system in development

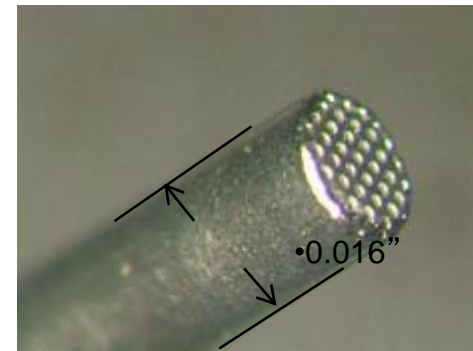


Applications

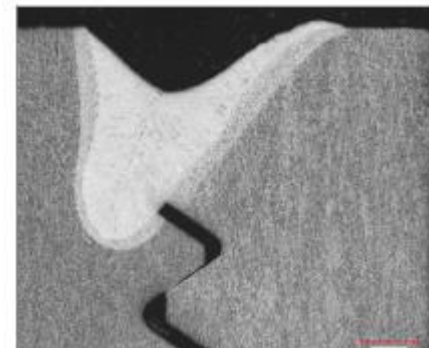
– Coil to hypotube (304SS)



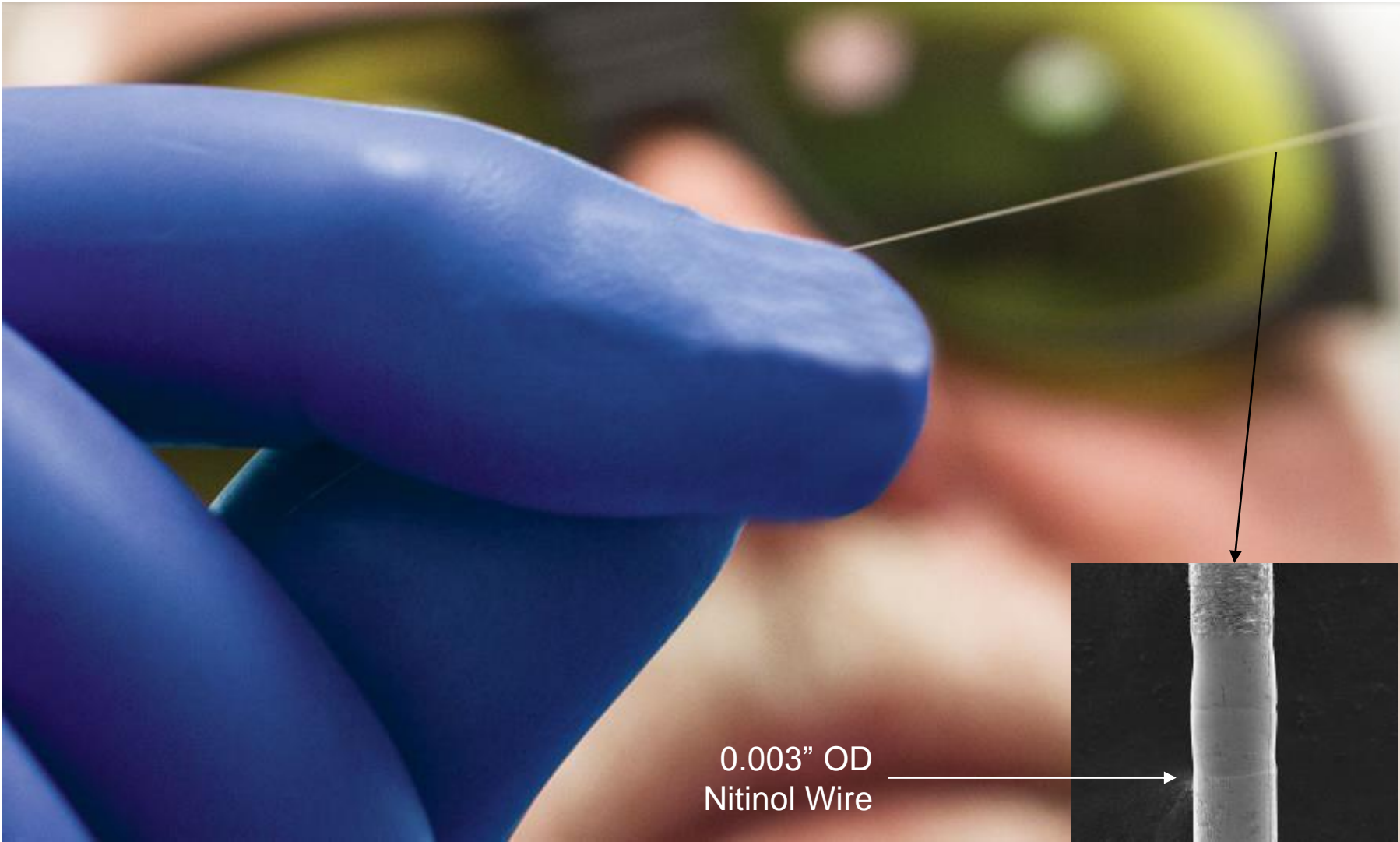
– Hypotube to filter (304SS)



– Spinal implant (Ti 6-4)

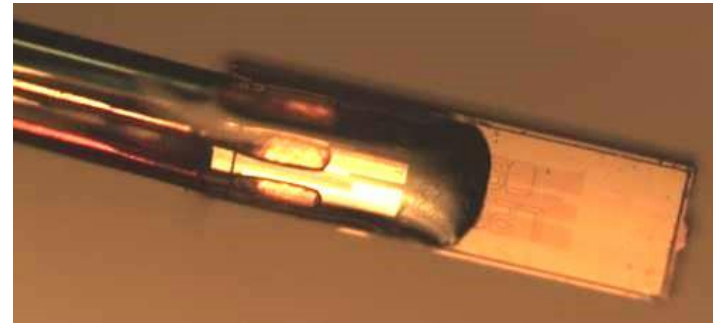


Laser Micro Welding



Micro Pressure Sensor

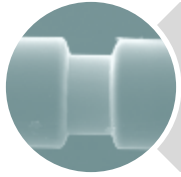
- Selective coating removal on trifilar wire
 - 0.001" copper wires
- Bonded to silicon pressure sensor
 - Copper to platinum solid state bond
- Encapsulated
 - Protect the bond from in-vivo environment



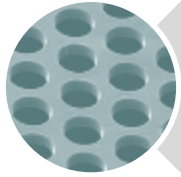
Presented with Permission of Silicon Microstructures Inc.

SMi
PRESSURE SENSORS

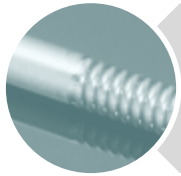
Technologies



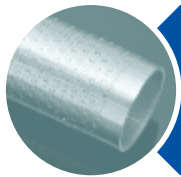
Ablating



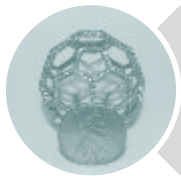
Drilling



Welding



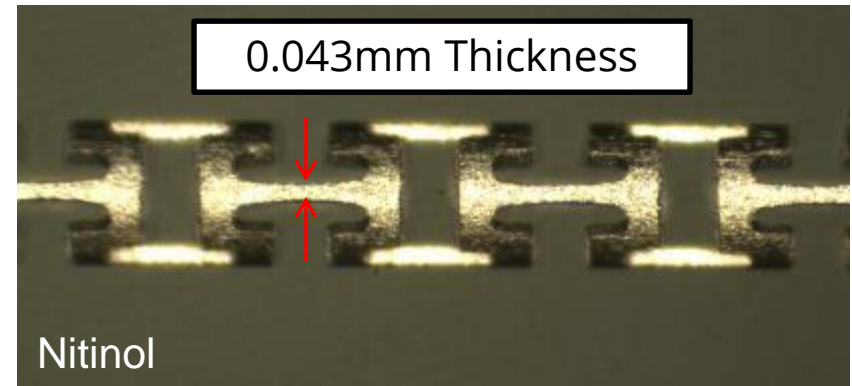
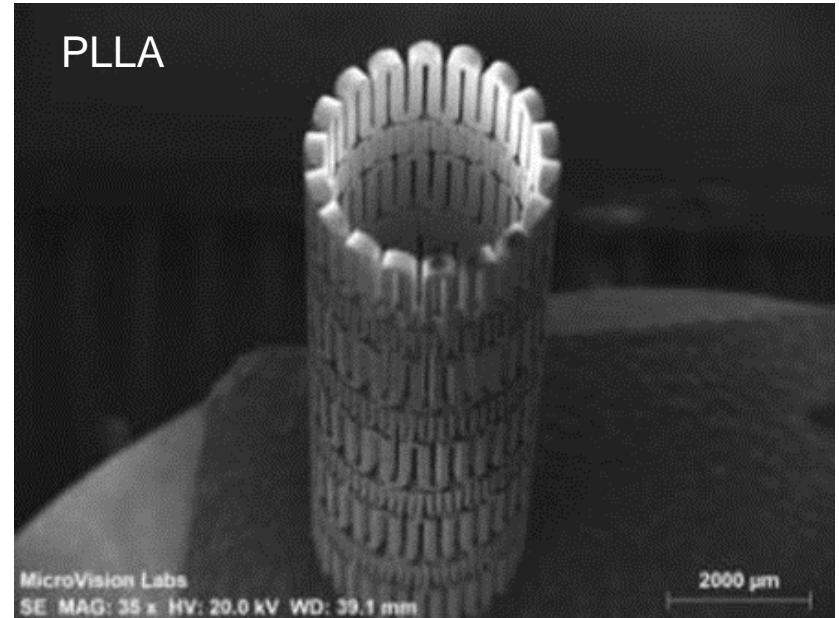
Cutting



Additive

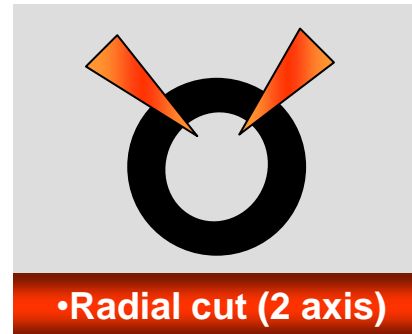
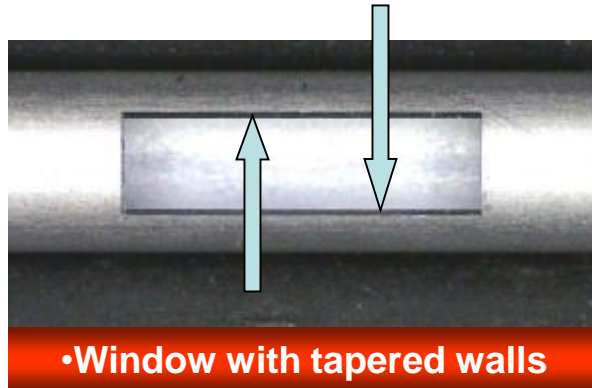
Why Use Laser Micro Cutting?

- Part Requirements:
 - Features down to 0.025mm
 - Custom part flexibility
 - Vary along length
 - Hypotube or flat
 - Metals and polymers

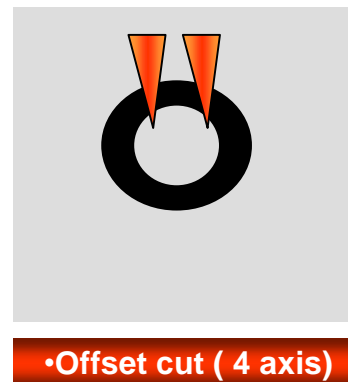
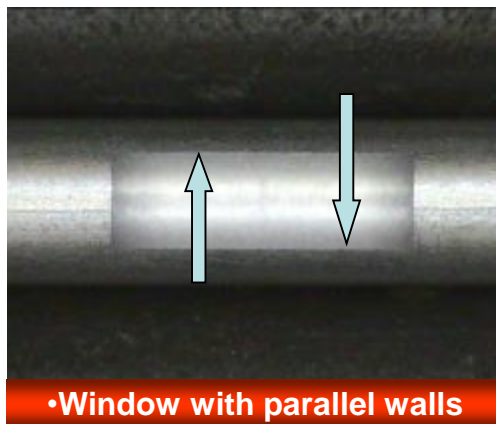


Types of Cut on Hypotubes

- On axis (Radial)



- Off axis (Offset)

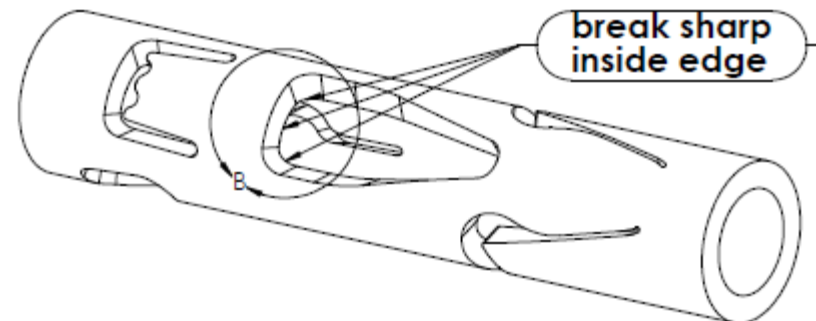
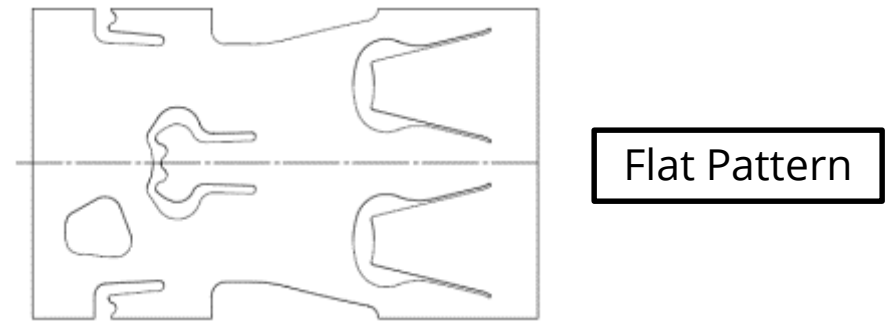
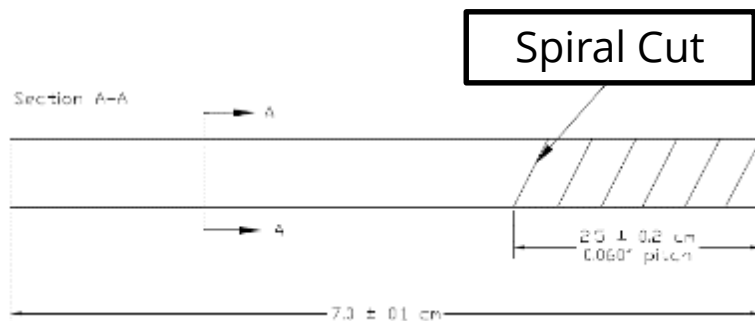


Hypotube Cutting Capability

- Metal or polymer
- Tube Dimensions
 - Variable OD and ID as long as the wall thickness is $\sim .010$ " or less.
 - OD can range from $.010$ " to $.375$ "
- Part length is limited to the length of raw material
 - This is typically 10 ft. or less
- Material
 - Straight without kinks or bends to process
 - 2.50 "- 4.00 " longer than the part in order to cut an entire part

Programming Requirements

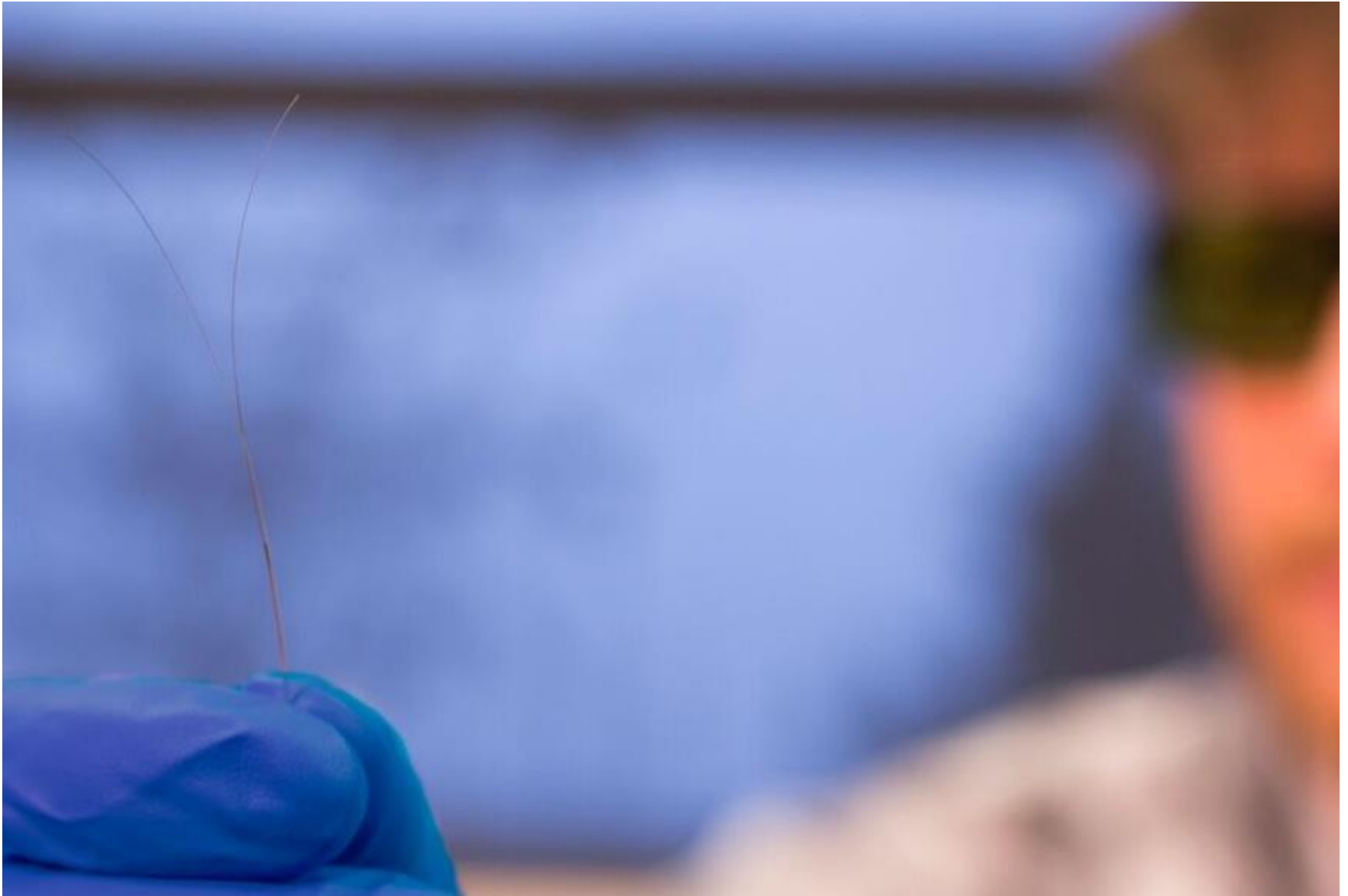
- Spiral cut patterns can generally be programmed from the drawing.
- Other geometry may require the customer to send a solid model or the flat pattern for programming.



Post Processing

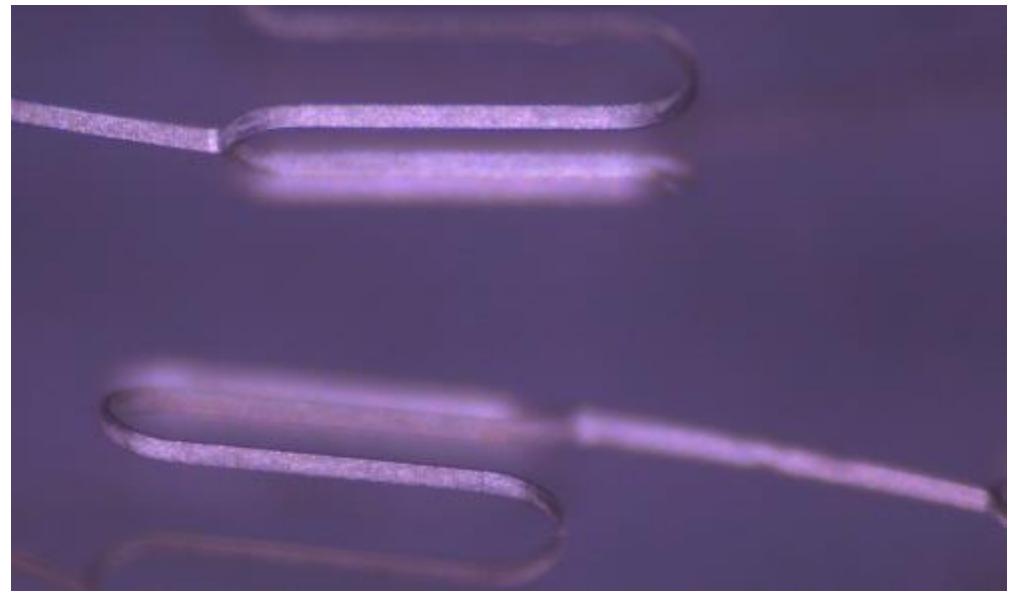
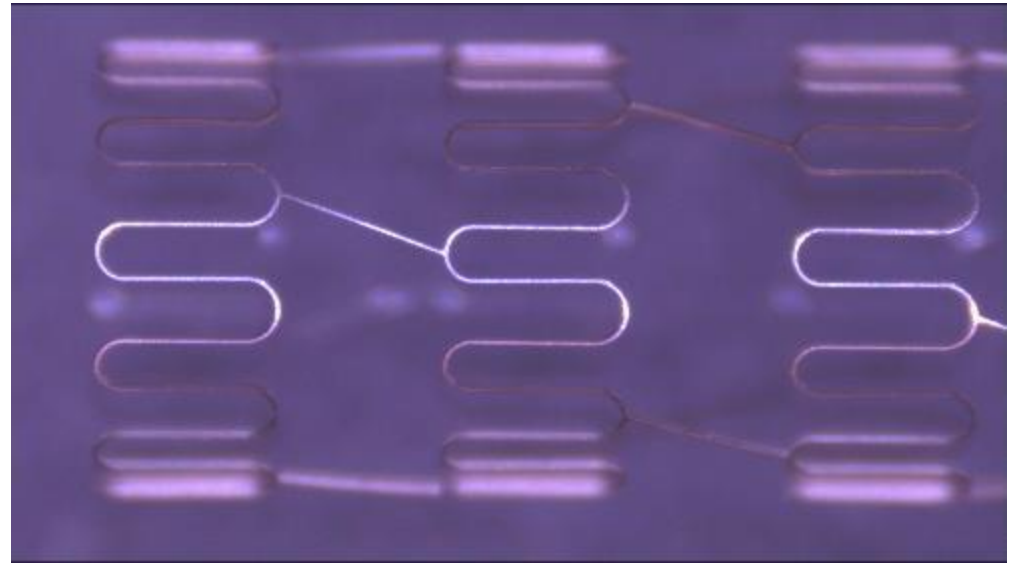
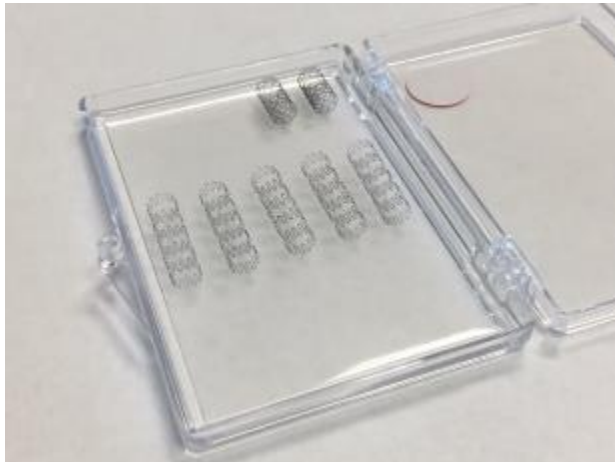
- Metal cut using long pulse (microsecond) lasers go through post processing to remove the oxide created near the cut surface.
- Parts can also be passivated to prevent oxidation (rusting) during storage. Passivation is the process of removing free iron from the surface of parts.
- Small ID parts (Less than .030" ID) require an additional flushing process to remove oxide and acids prior to drying.

Laser Micro Cutting



Nitinol Stent Cutting with 25 micron struts

- 25 micron strut with single micron standard deviation on geometry
- No thermal damage
- Custom laser system design

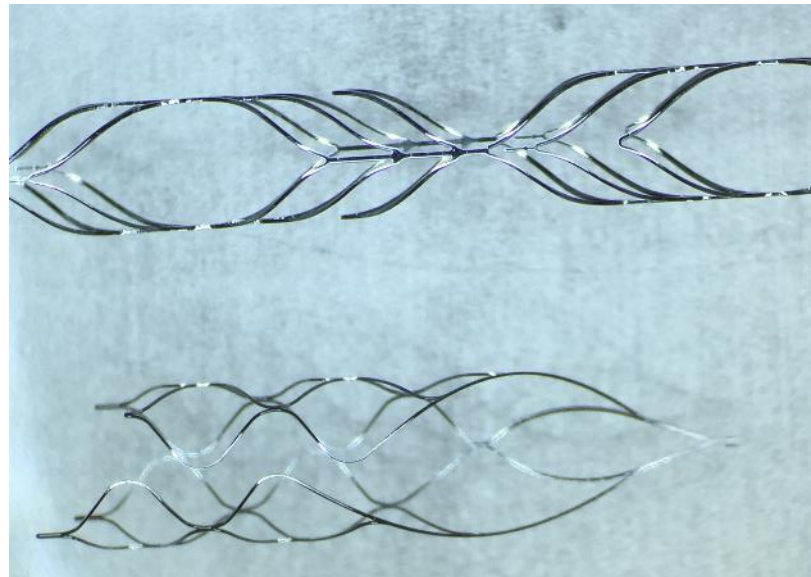


Nitinol – Heat Set and Electropolish

Current: Prototype

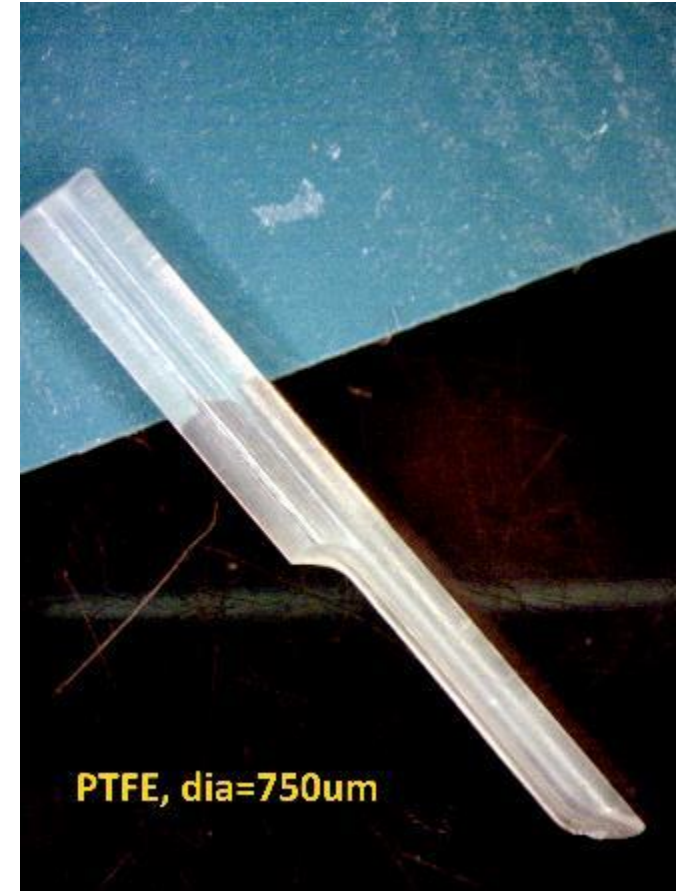
- Heat Set
 - Fluidized Sand Bath
- Part Cleaning
 - Oxide Removal
- Electropolish
 - Refrigerated Epolish

2017: Production



Polymer Cutting

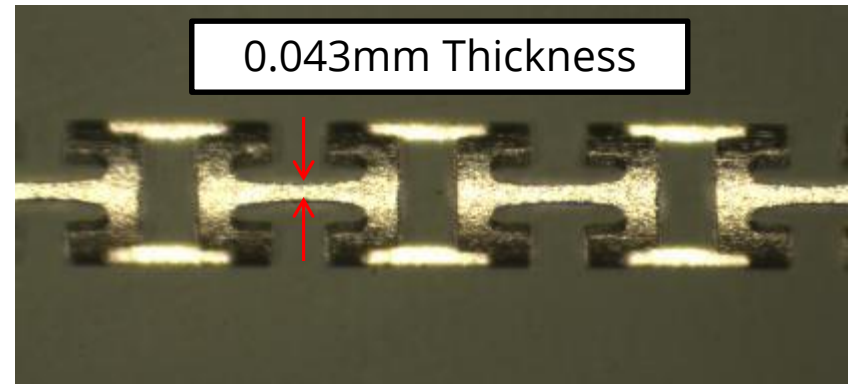
PEEK dia=2.5mm, wall=150um



PTFE, dia=750um

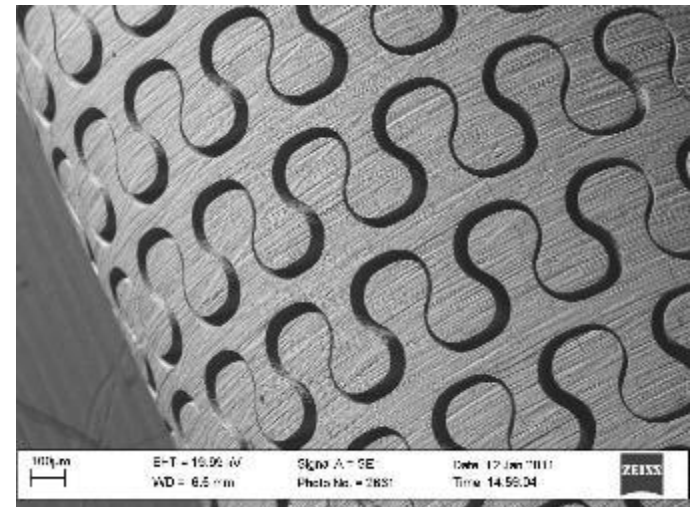
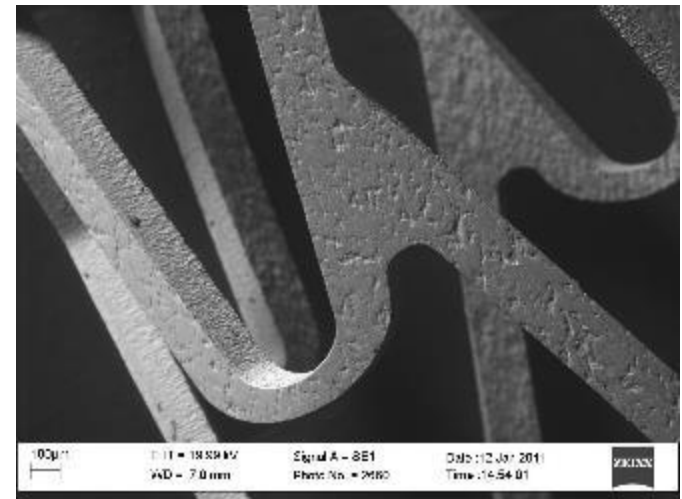
Nitinol Hypotube Cutting

- Hypotube (0.0135" OD)
- Life science applications
 - Neurovascular stents
 - TAVR Frames & Baskets
 - Delivery catheter components
 - Micro implants



Stainless Steel Hypotube Cutting

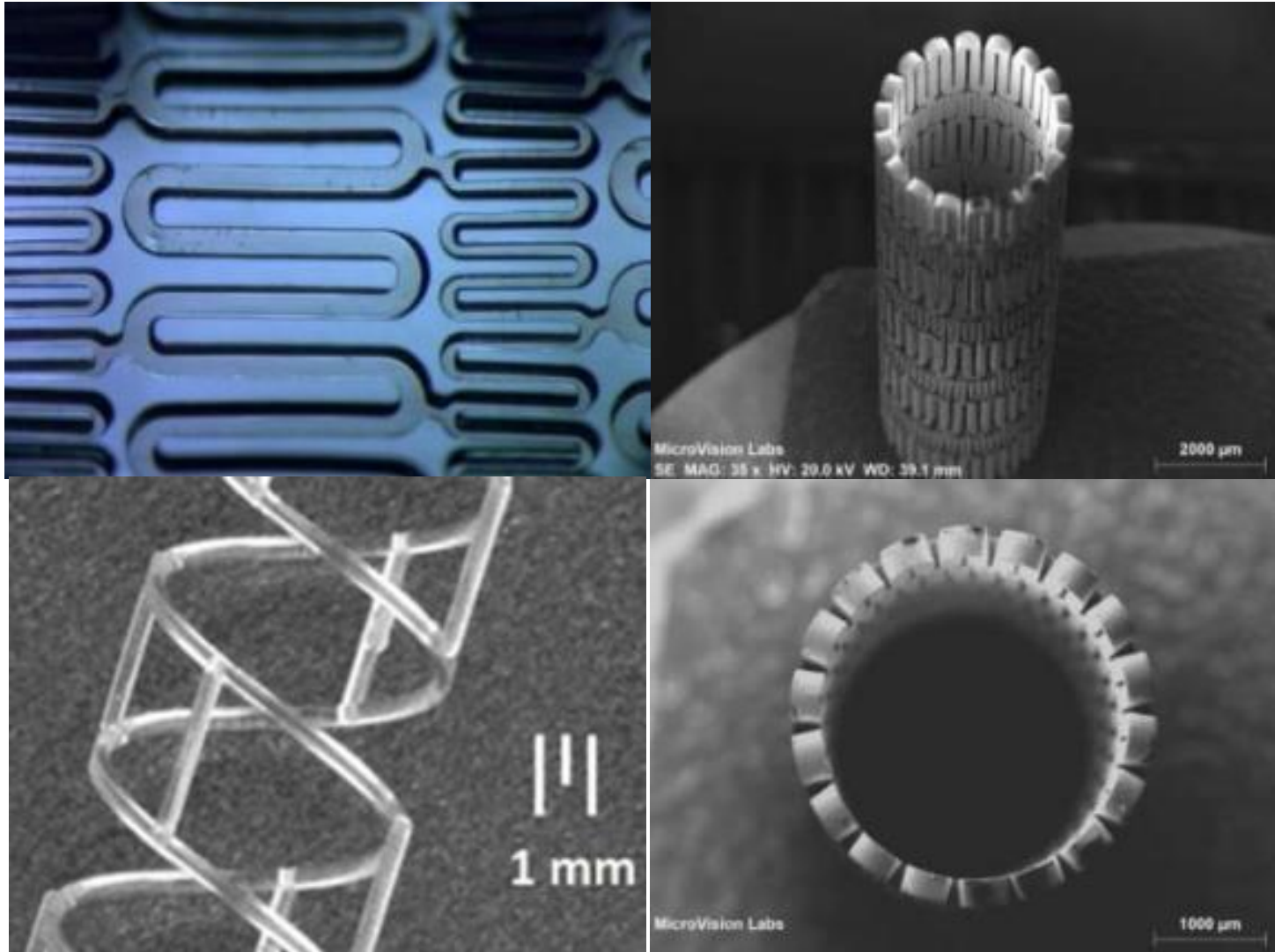
- Stent Structure
 - 0.040" OD
- Flexible Hypotube
 - Interlocking features
 - 0.040" OD
- Life Science Applications
 - Neurovascular delivery system components
 - Transcatheter delivery system components



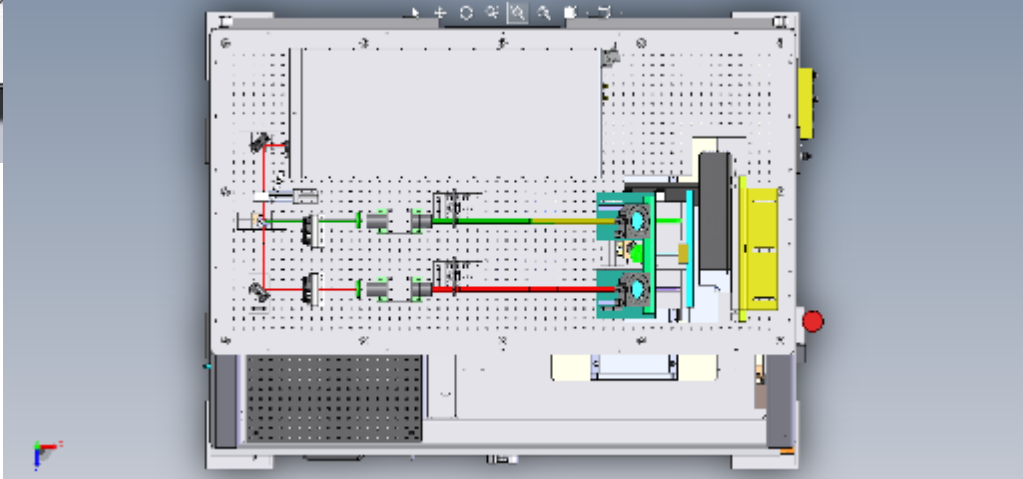
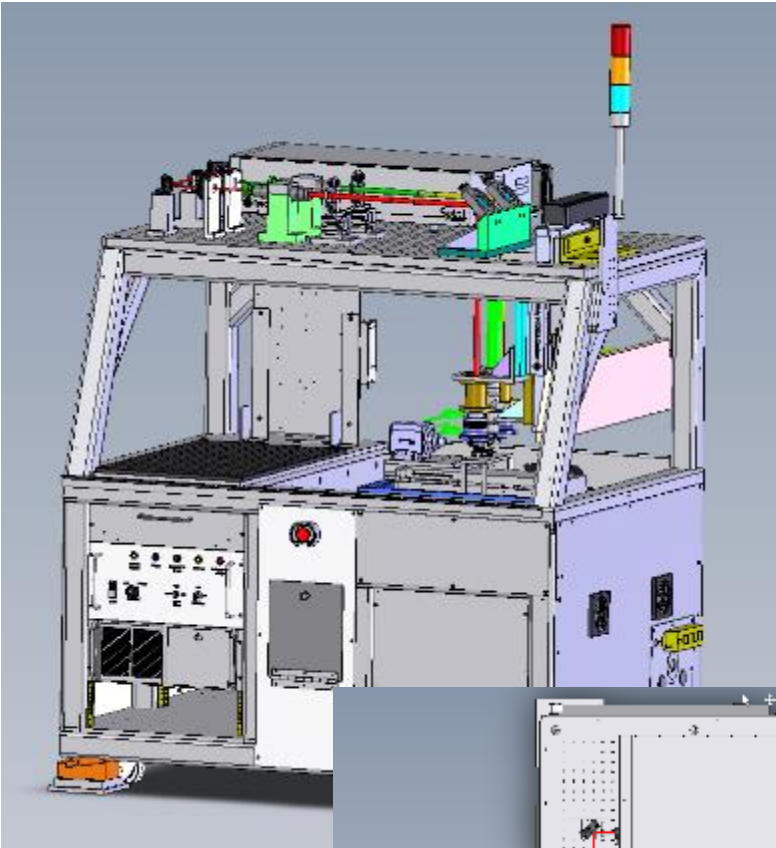
Applications – Stainless Steel Hypotube



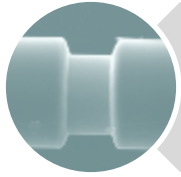
Applications - Bioresorbable polymer



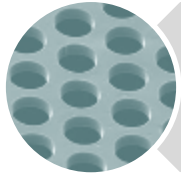
Cutting System – Dual Wavelength Femtosecond



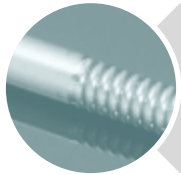
Technologies



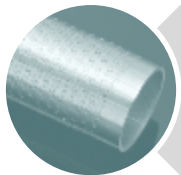
Ablating



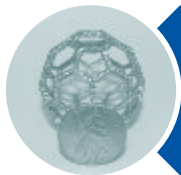
Drilling



Welding

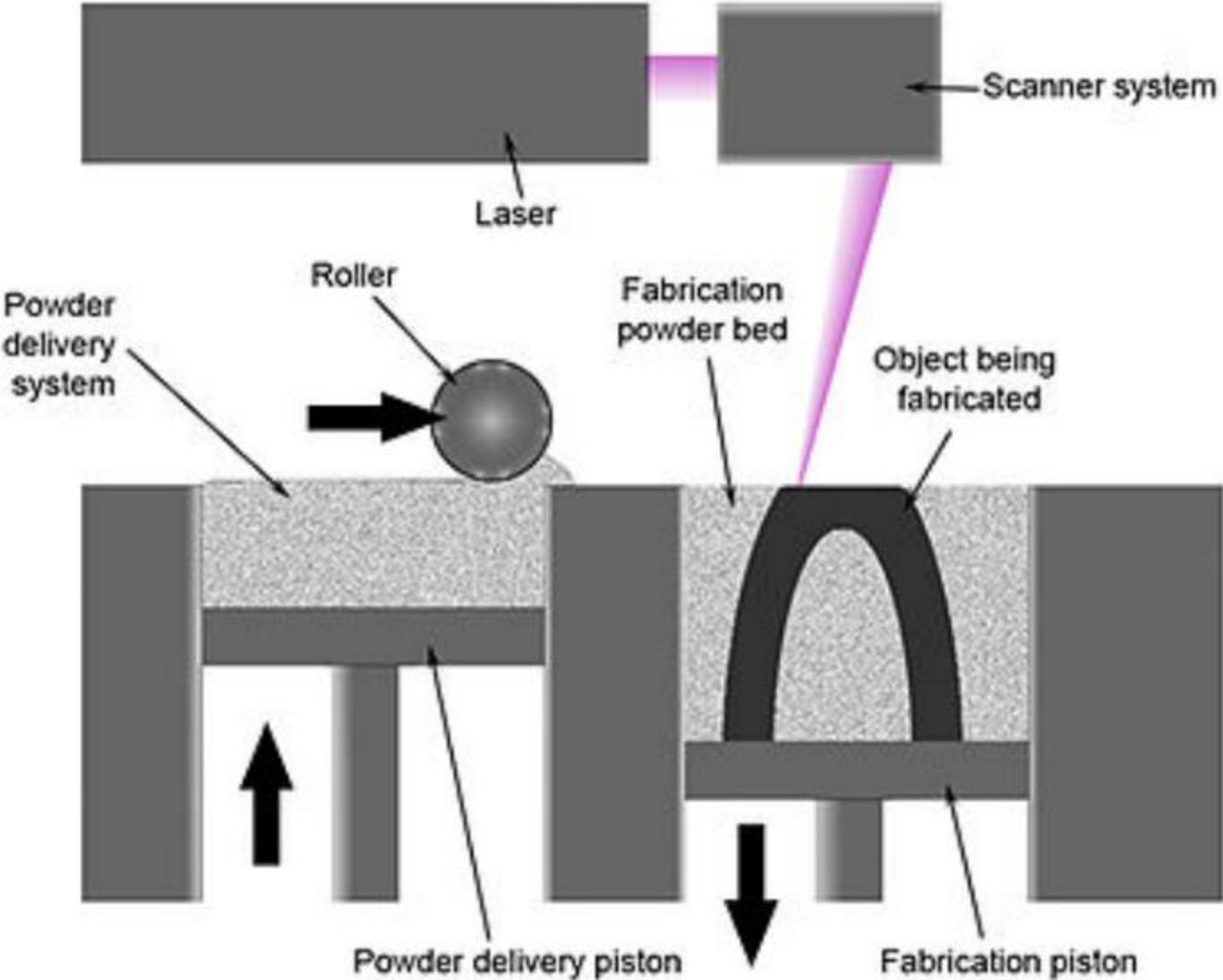


Cutting



Additive

Selective Laser Sintering



Metal Additive Manufacturing

- Myth versus Reality
 - Myth
 - CAD File
 - Print
 - Reality
 - CAD Design with process knowledge – material, supports, process limitations, overhangs etc.
 - Part Build
 - Heat Treat and/or Hot Isostatic Press
 - Remove from Build Platter
 - Remove Support Structures
 - Post Machine, Polish
 - Geometrical Inspection, CT Scan for Internal Features



Image Courtesy of Morris Technologies

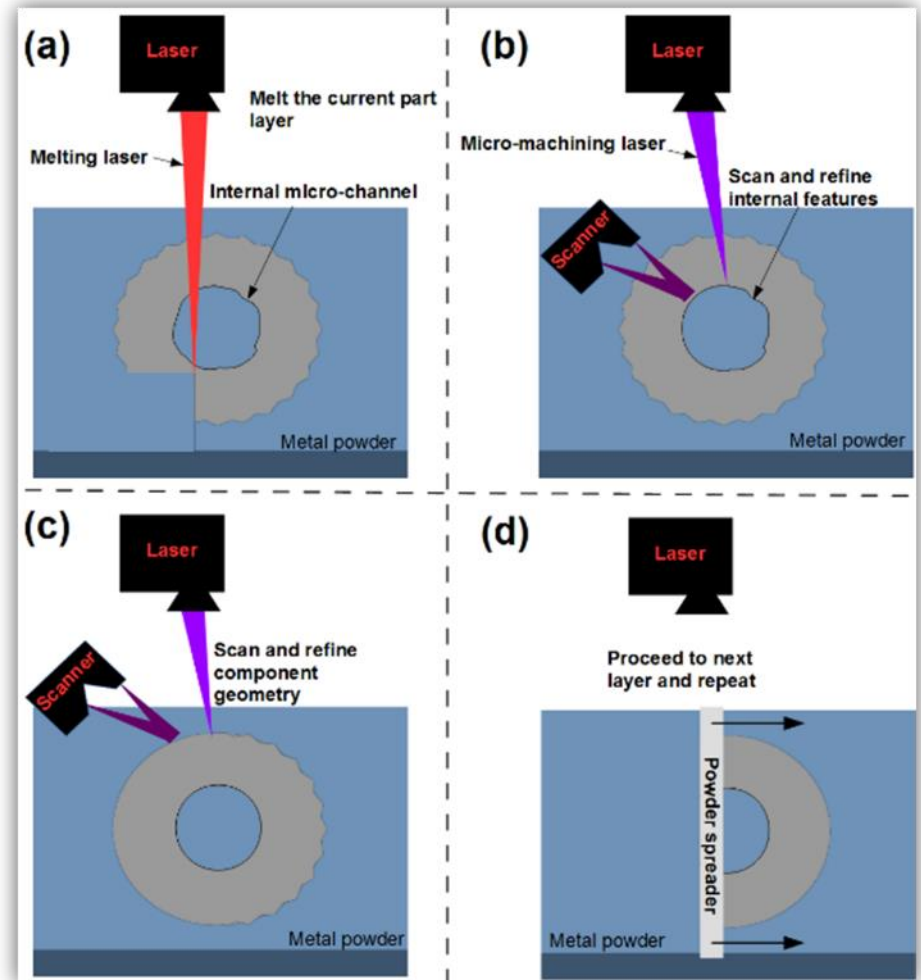
Metal Additive Manufacturing

- Cobalt Chrome
- Titanium
- Stainless Steel
- Nickel-Based Alloys
- Refractory Materials



Additive + Subtractive

- **Problem:** Small features remain difficult for current AM technologies without post-machining processes
- **Solution:** A new additive/subtractive hybrid approach that combines powder bed additive manufacturing with laser micromachining processes; layer-by-layer

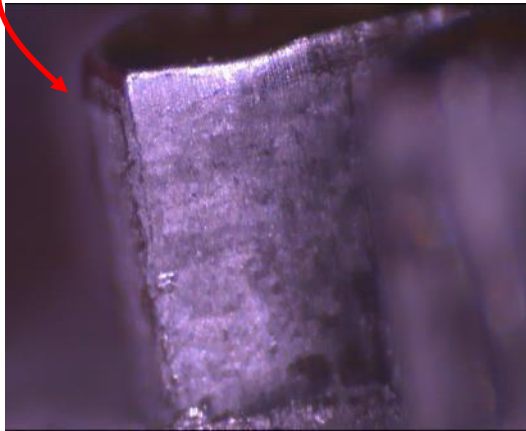


Patent Pending

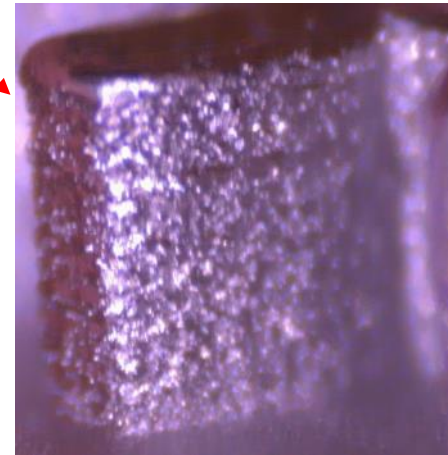
Gear Example - Cobalt Chrome



Additive + Subtractive

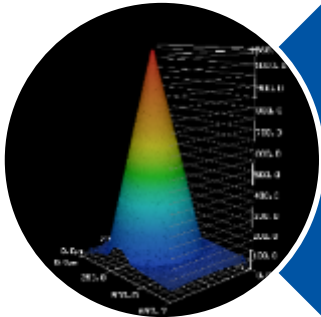


Additive Only



Patent Pending

Business Model



Advanced Technology Group

Next Generation Laser Micro Manufacturing
Technology



Quick Turn Prototypes



Contract Manufacturing

Volume Production
Custom Laser Systems